

Advanced LIGO Photodiode Development

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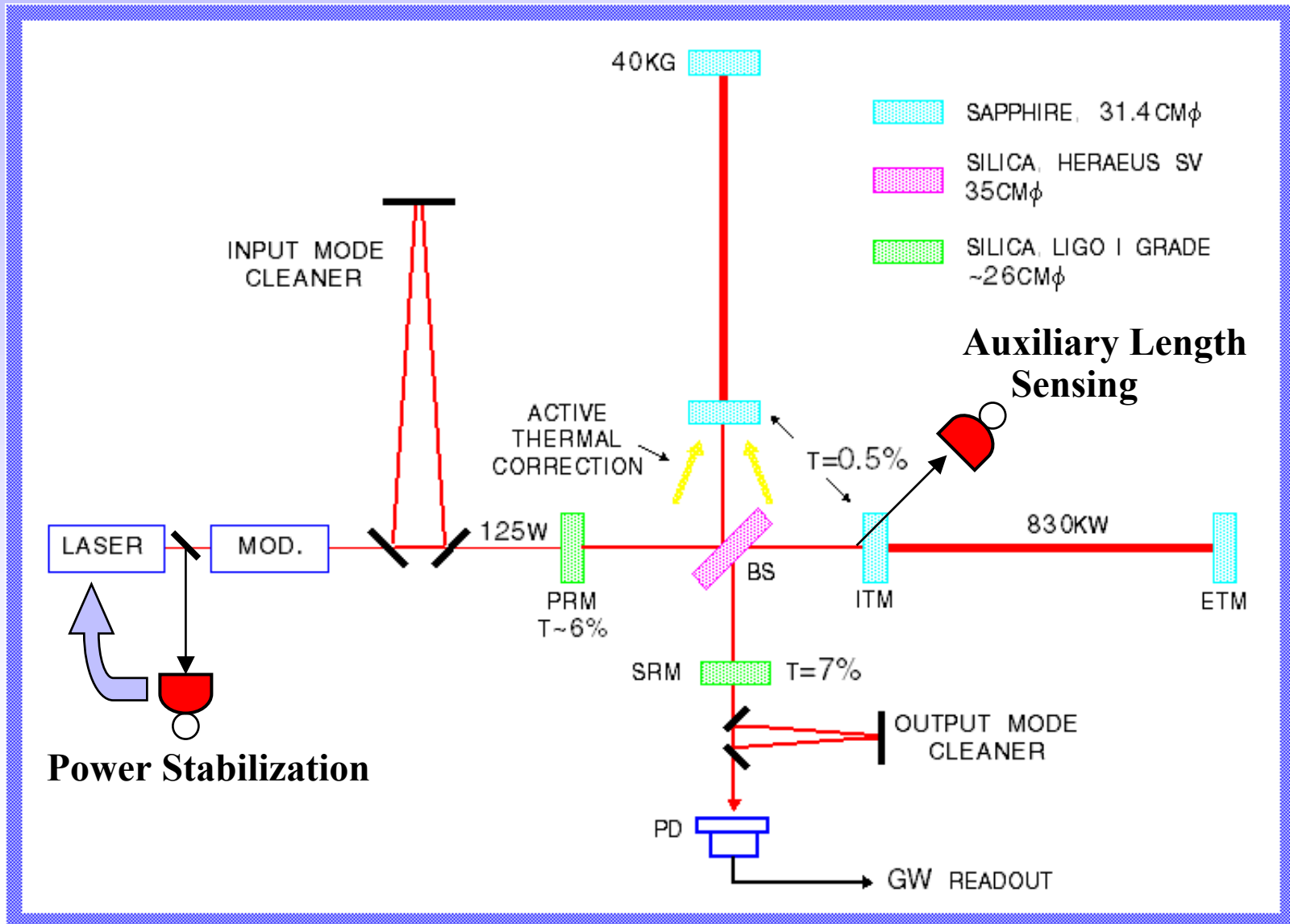
Hannover, Germany

August 20th, 2003

LIGO-G030495-00-Z

- **Motivation & Introduction**
 - AdLIGO PD Specifications
 - Device Materials and Design
 - InGaAs vs. GaInNAs
- **Device Results**
 - Thinned Device QE
 - InGaAs & GaInNAs I-V
 - 2 μ m Thick GaInNAs Absorption
- **Predictions**

Advanced LIGO Schematic



Photodiode Specifications

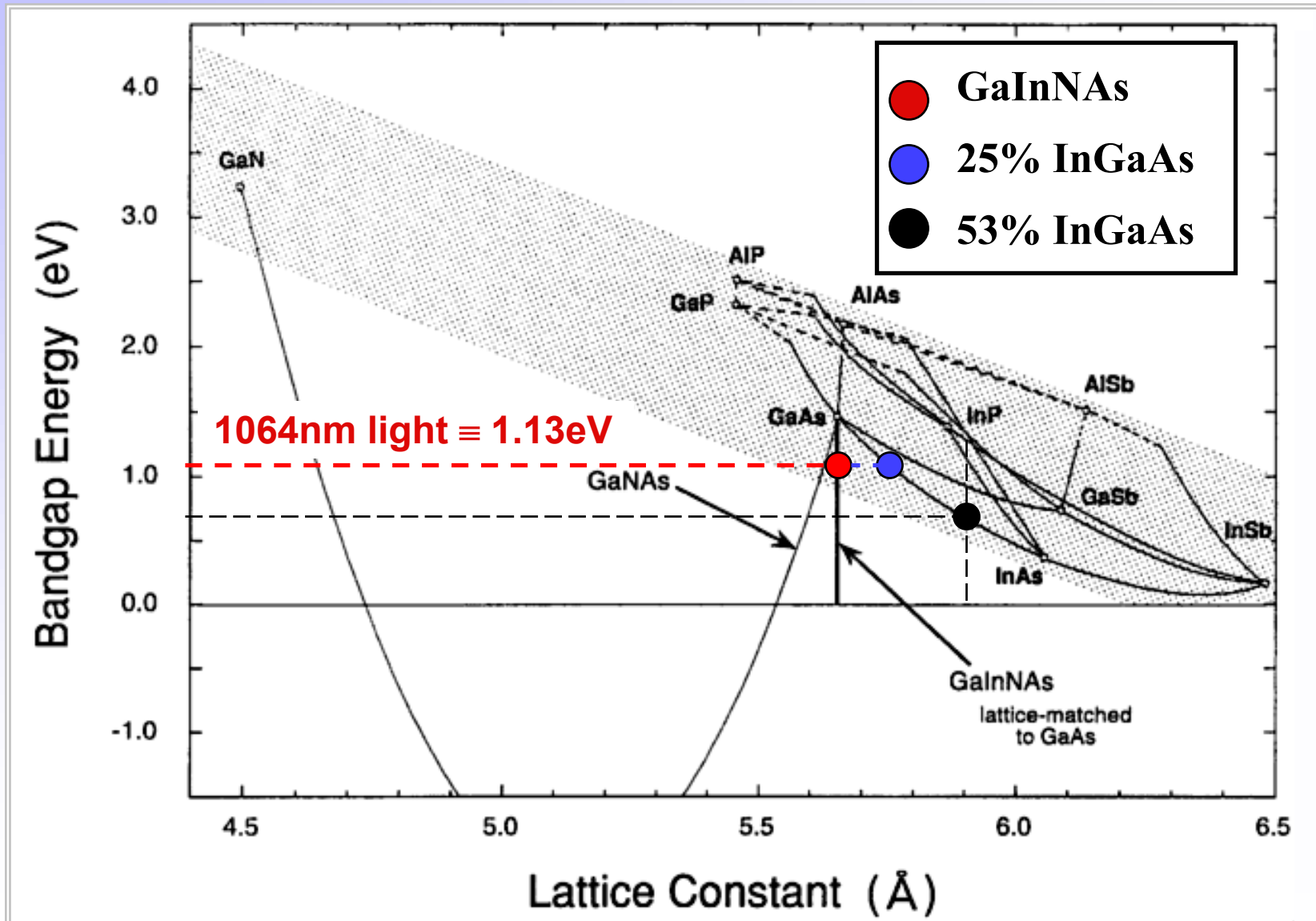
	LIGO I		Advanced LIGO	
Detector	Bank of 6PDs	Power Stabilization	RF Detection	GW Channel
Steady-State Power	0.6 W	1W/ η	10 - 100mW	30mW
Operating Frequency	~29 MHz	100 kHz	200MHz	100 kHz
Quantum Efficiency	> 80%	η	> 80%	> 95%

e.g. $1W/0.70=1.43W$

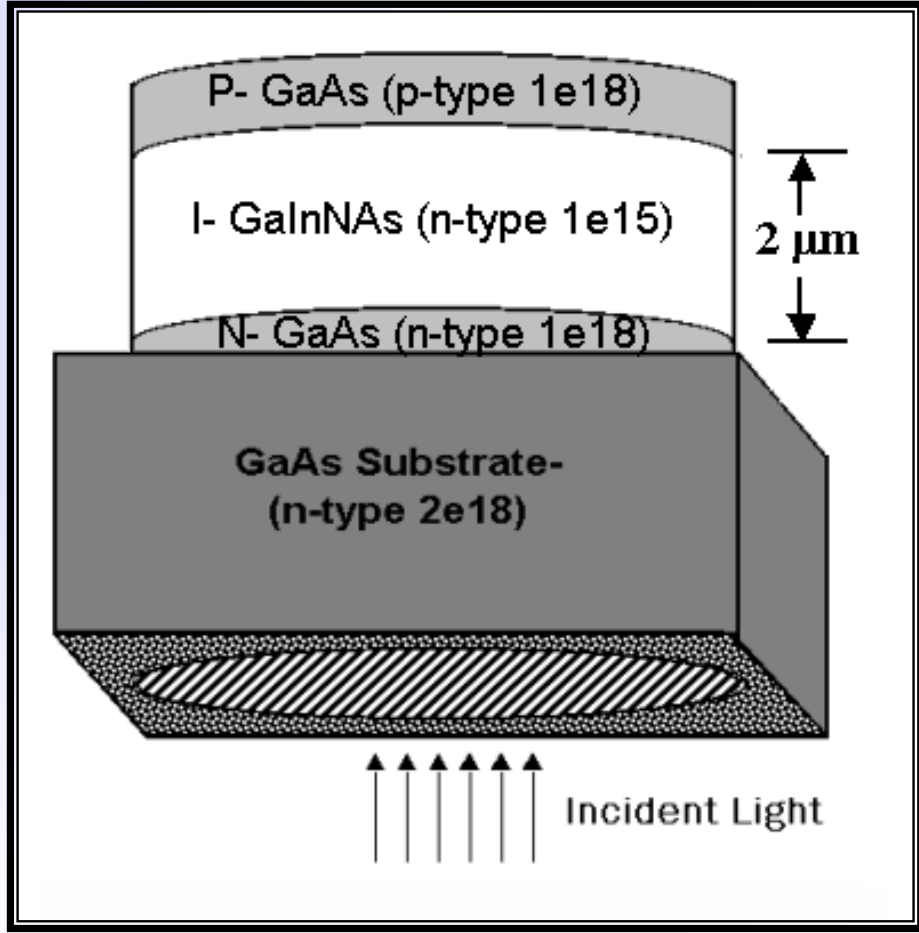
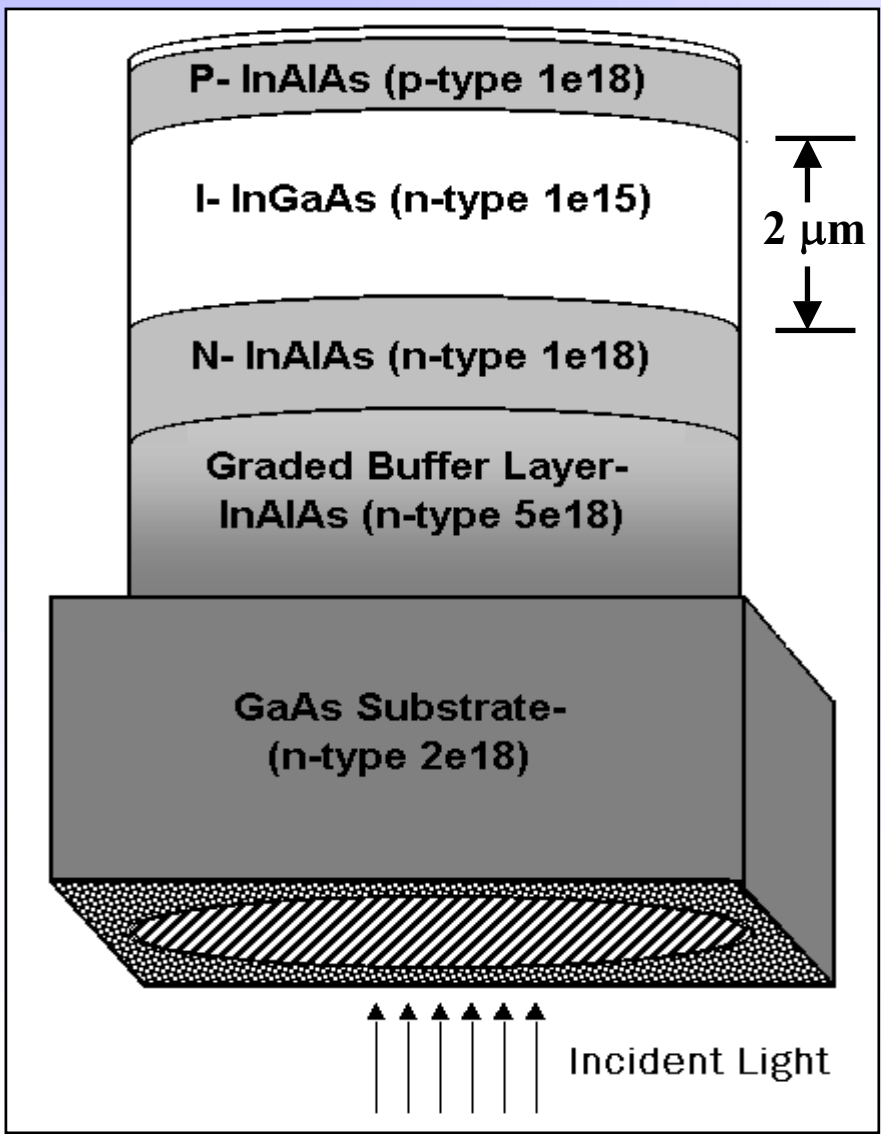
Resonating Tank Circuit

Thinned Substrate

GaInNAs vs. InGaAs

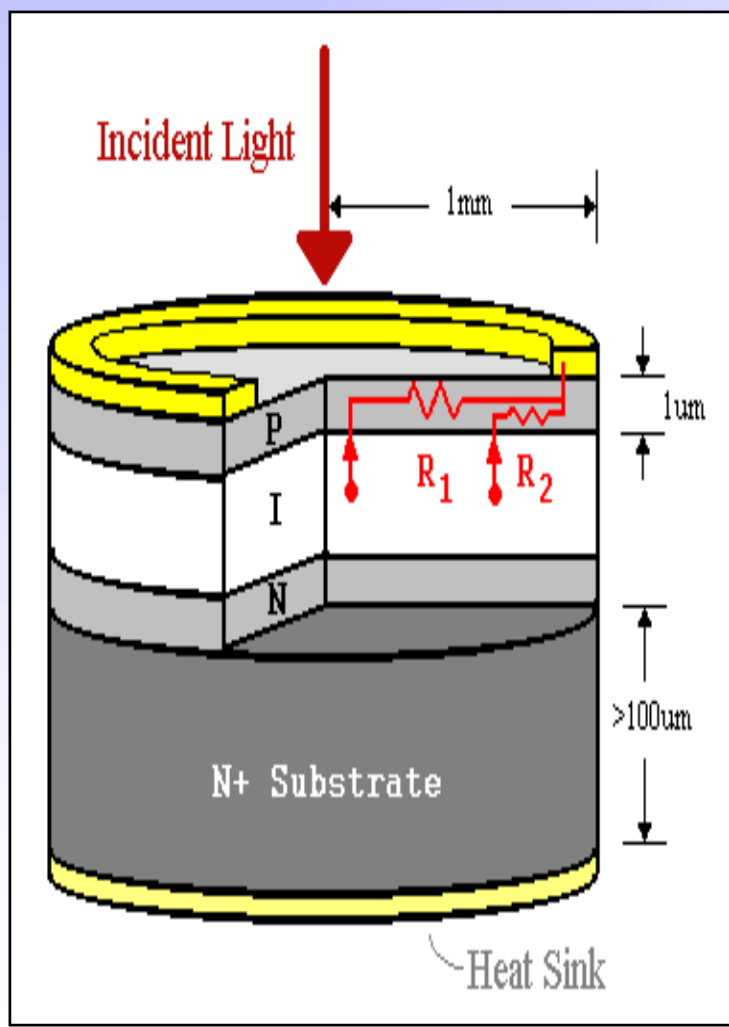


InGaAs vs. GaInNAs PD Designs

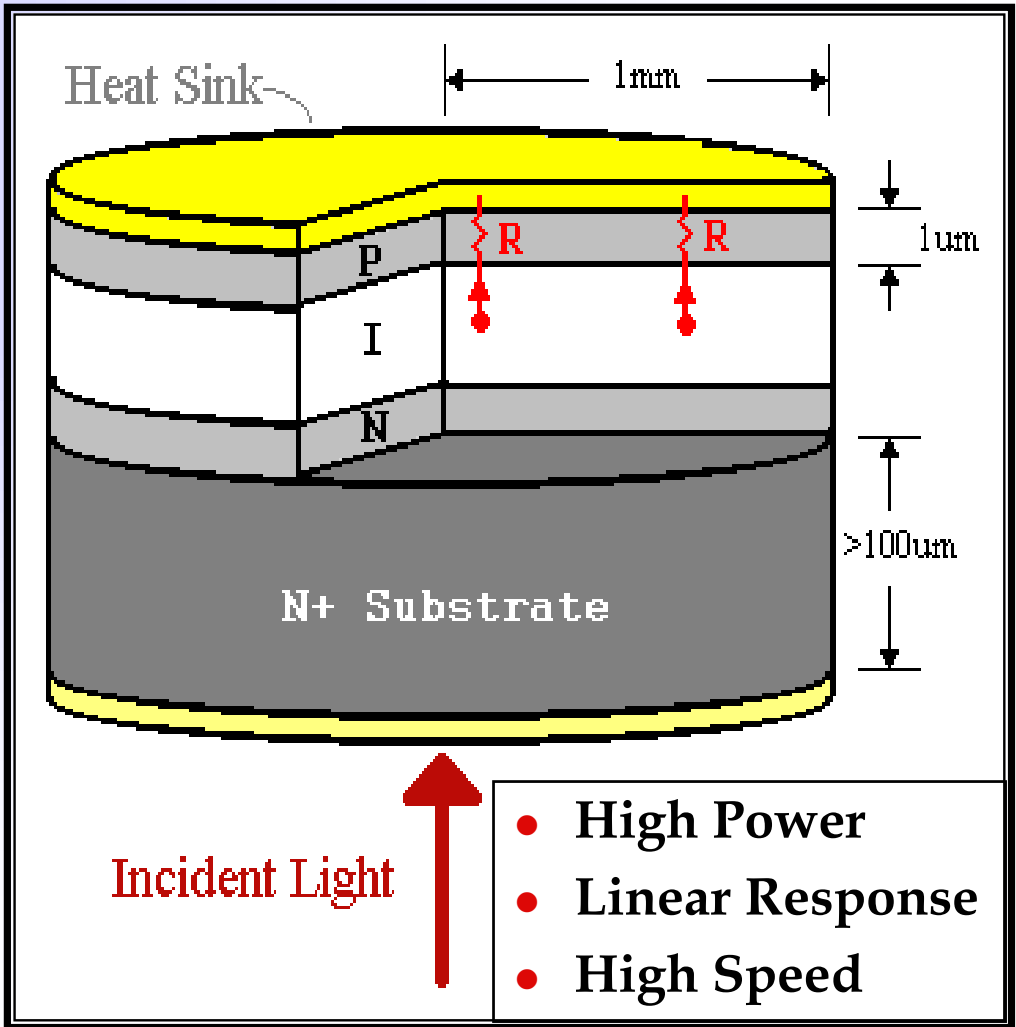


**GaInNAs lattice-matched
to GaAs!**

Rear-Illuminated PD Advantages



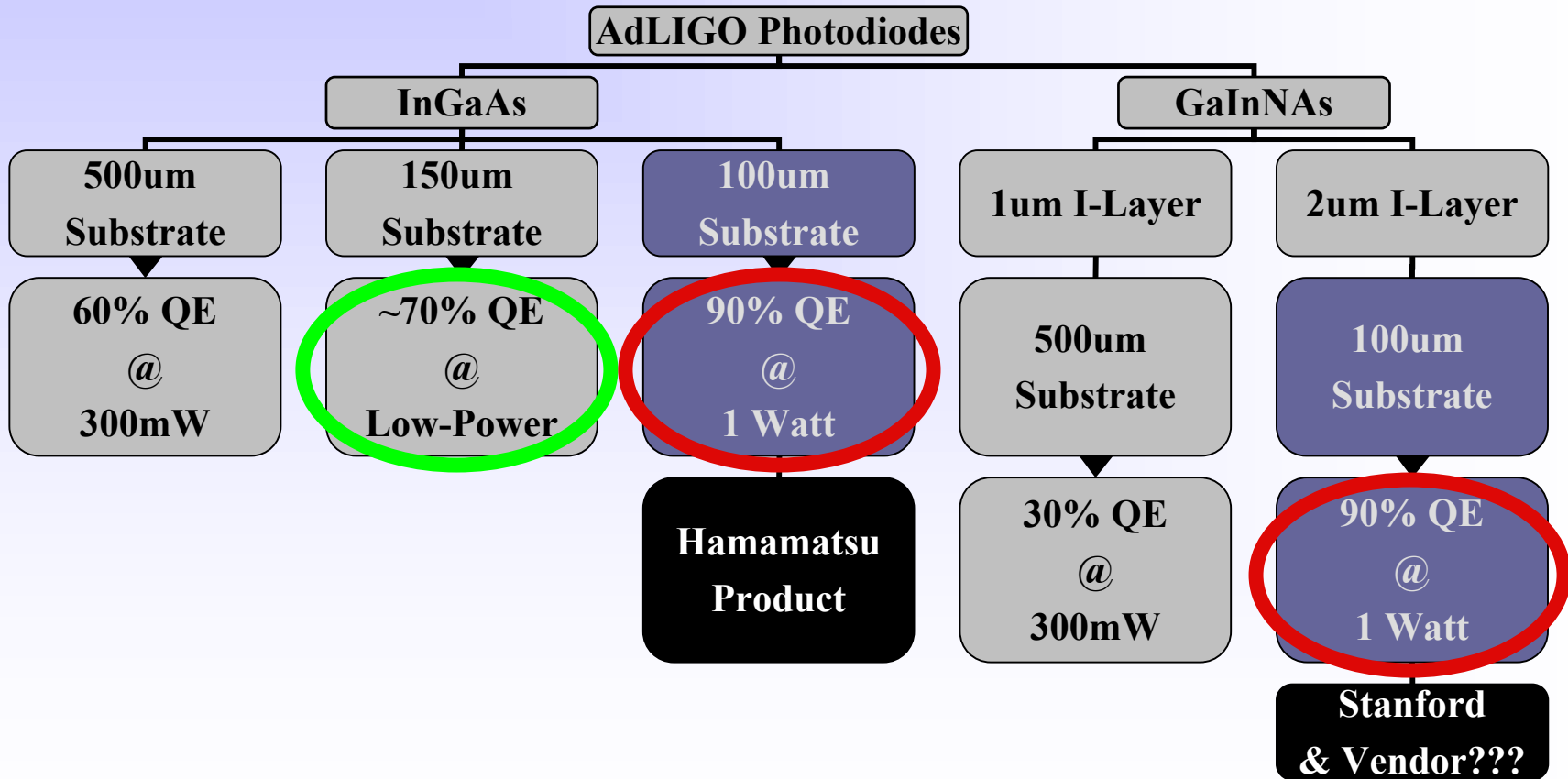
Conventional PD



- High Power
- Linear Response
- High Speed

Adv. LIGO Rear-Illuminated PD

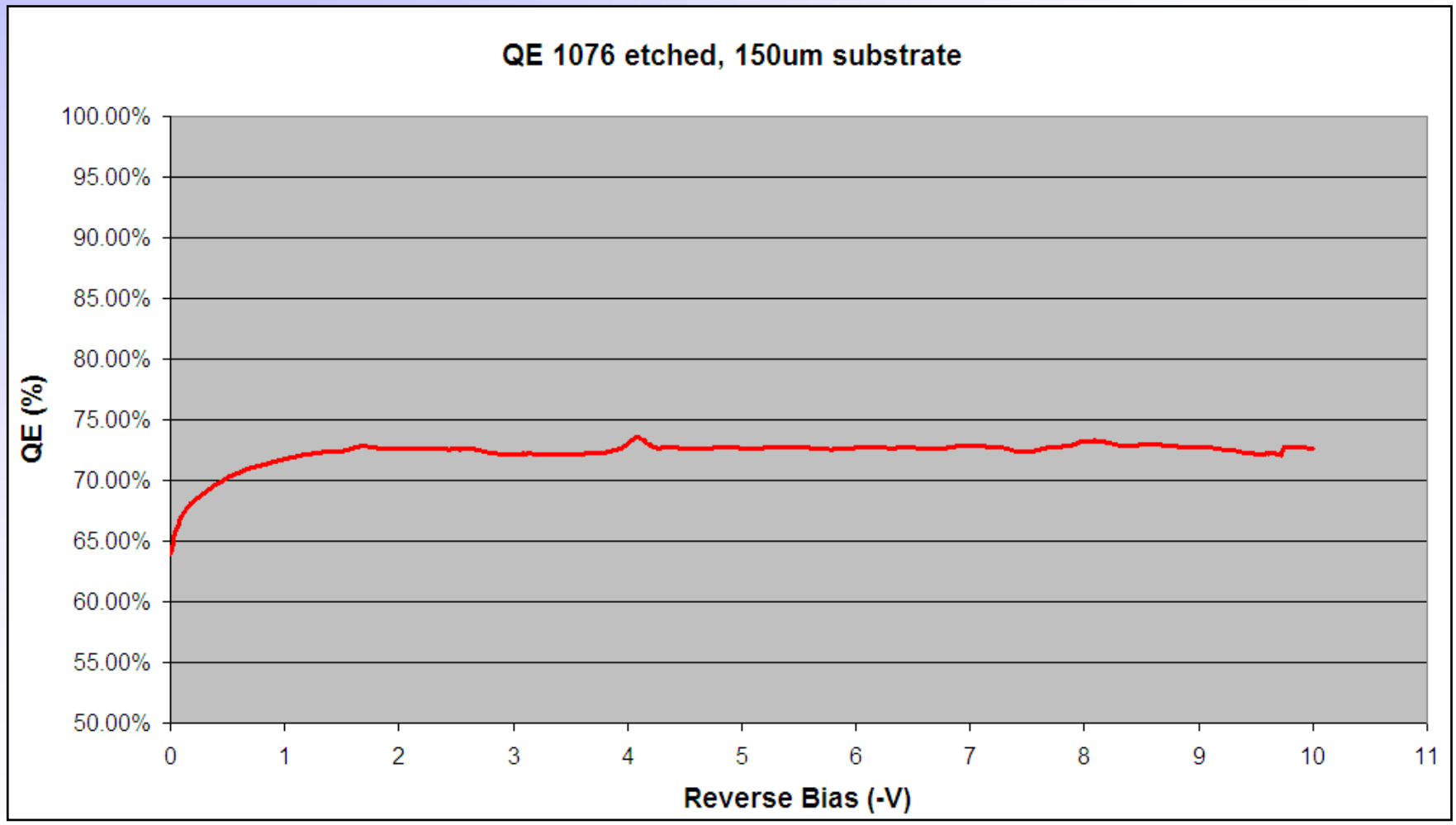
Development Flow-Chart



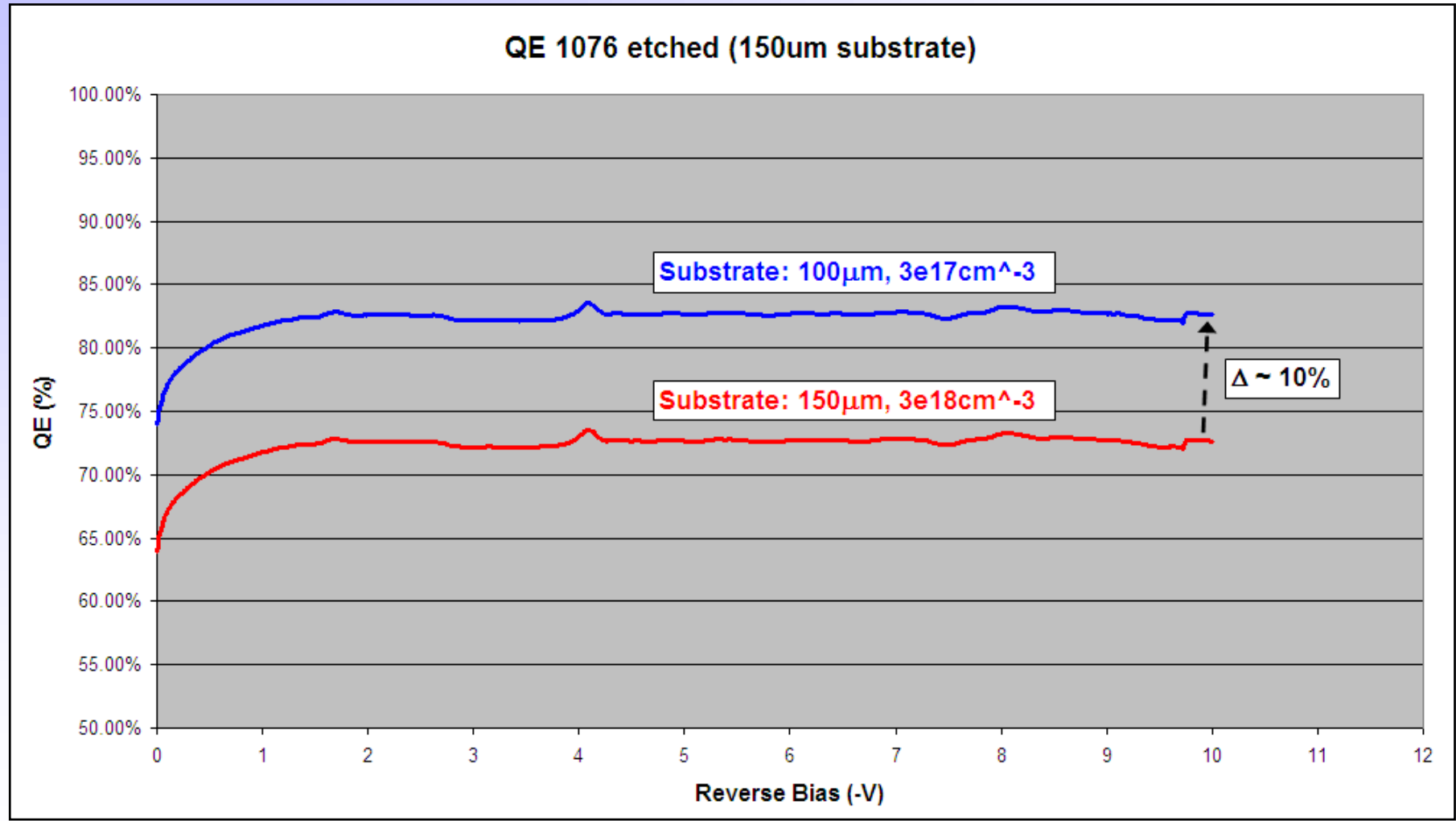
Thinned Device QE (10mW)



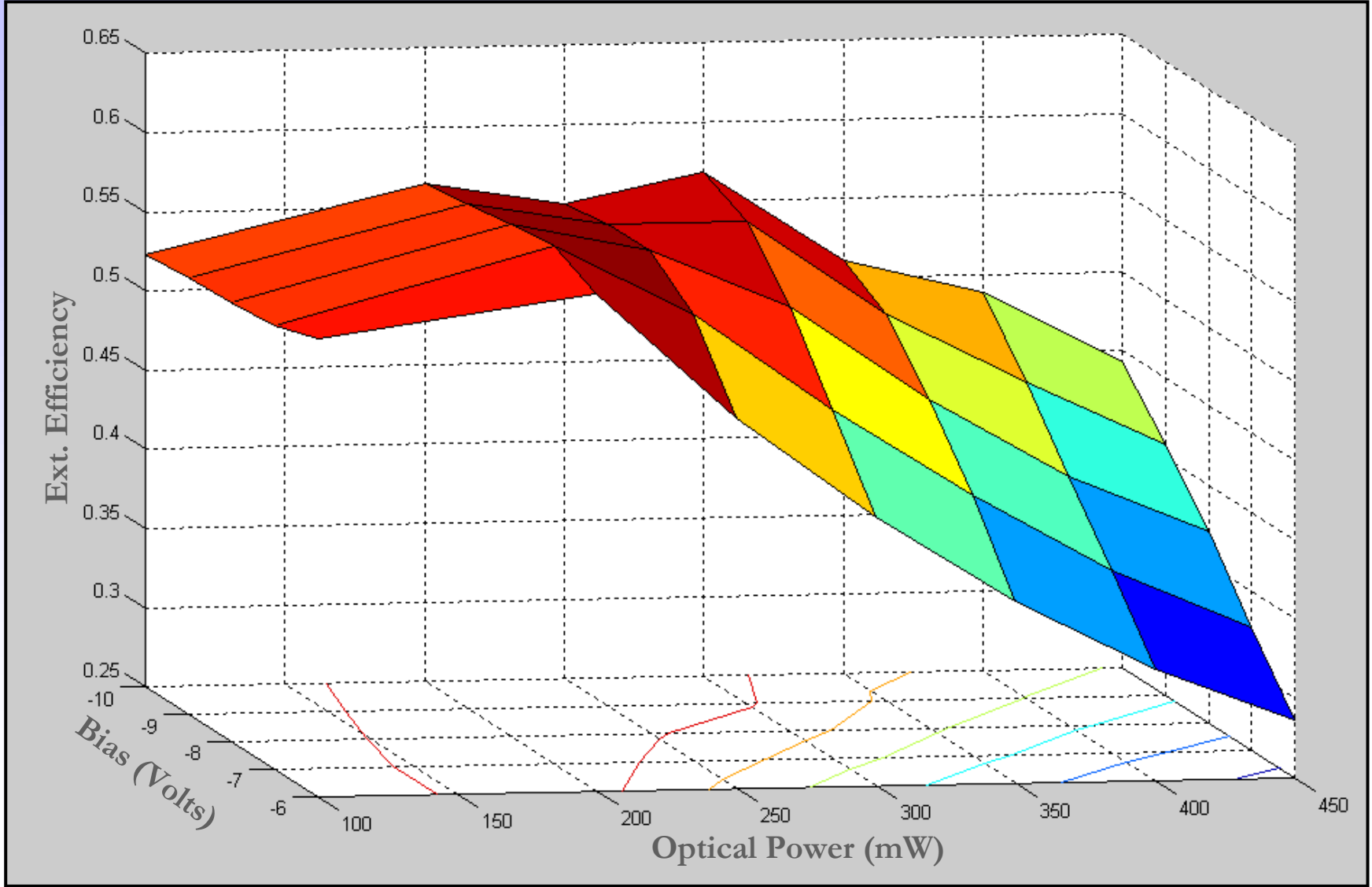
QE 1076 etched, 150um substrate



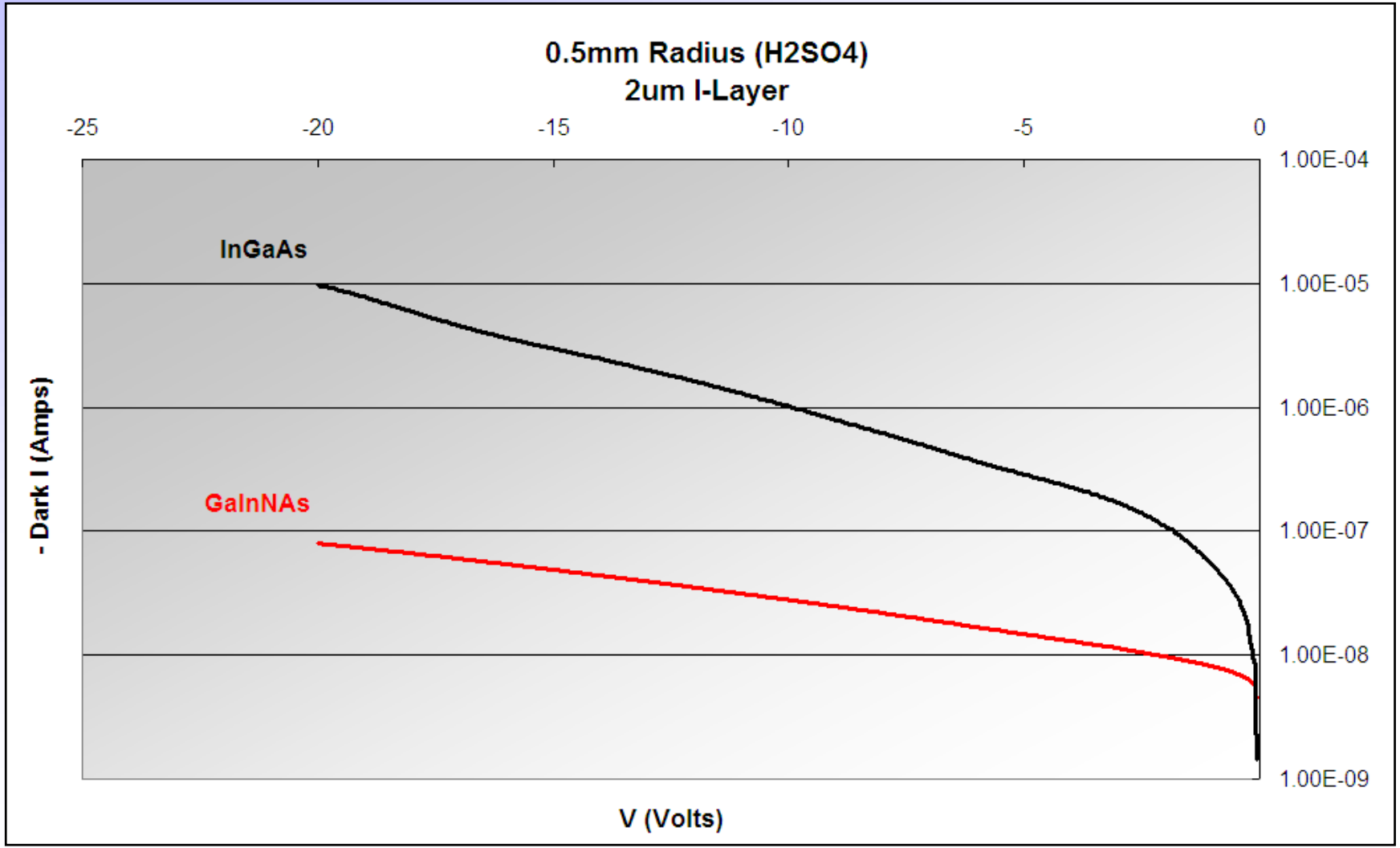
Thinned Device QE (w/ 100 μm , 3e17cm⁻³ Substrate)



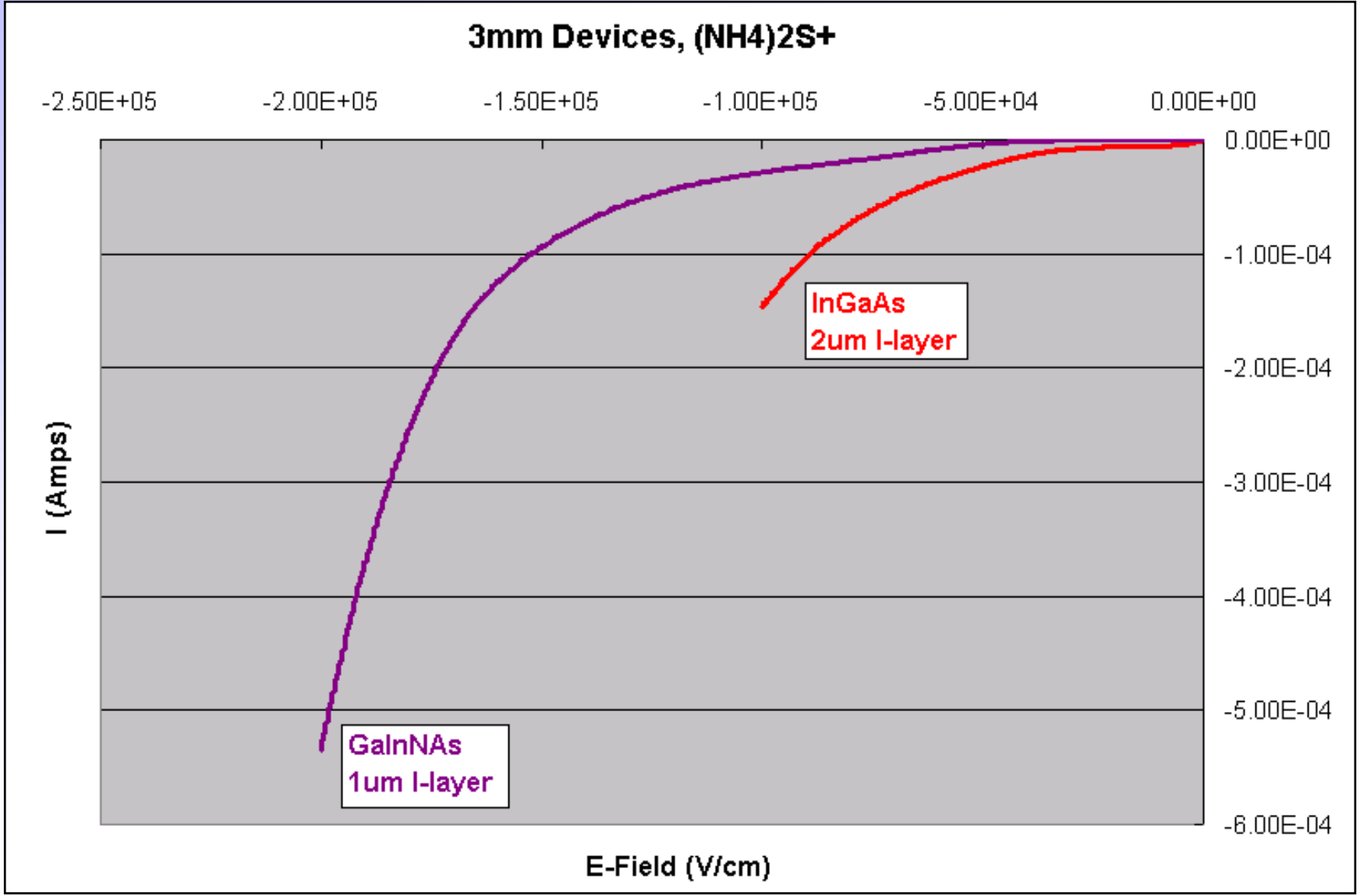
DC Device Efficiency (w/ ARC)



InGaAs vs. GaInNAs Dark Current



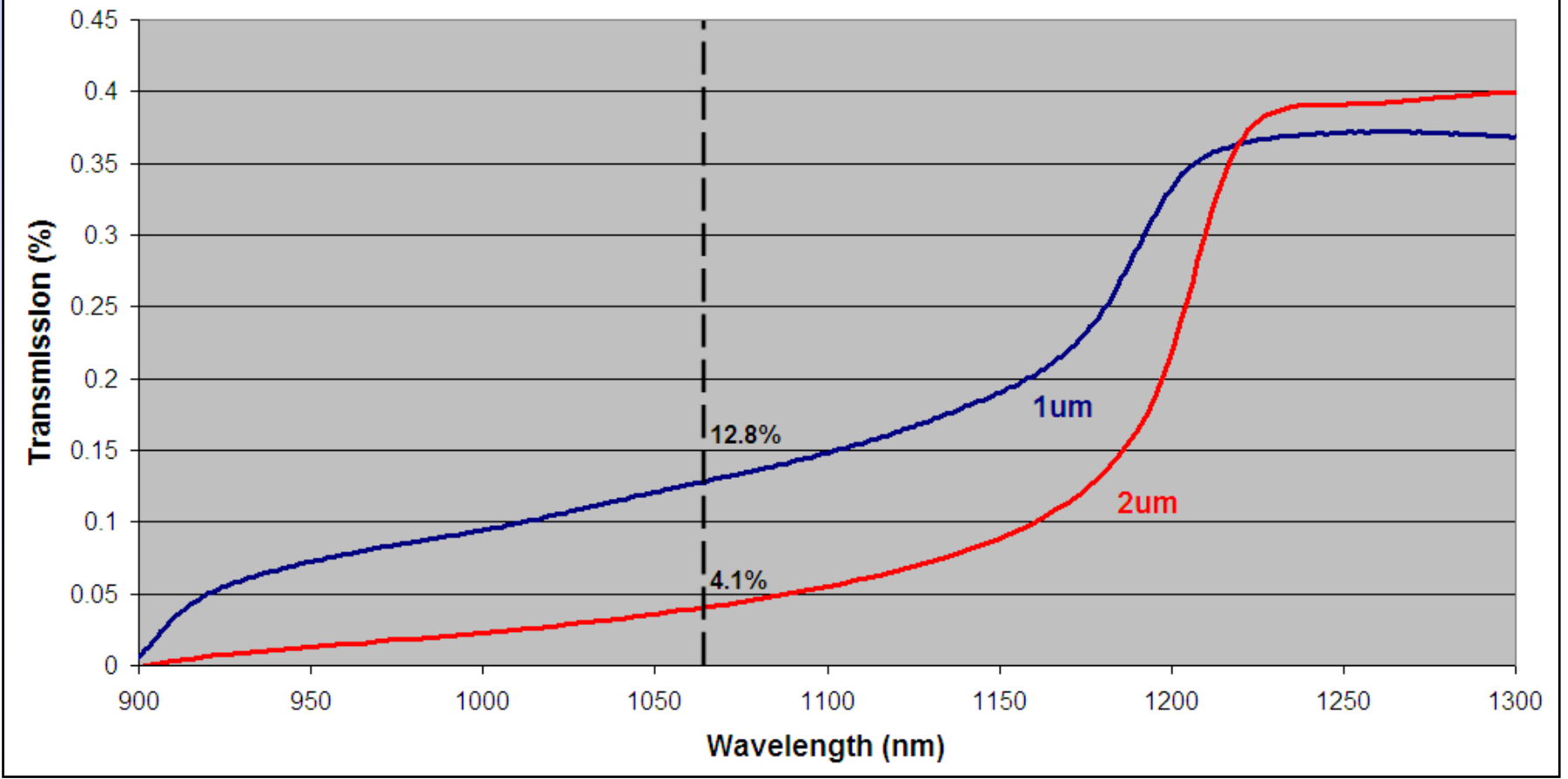
InGaAs vs. GaInNAs Dark Current



GalnNAs Device Transmission



1um vs. 2um GalnNAs I-Layers



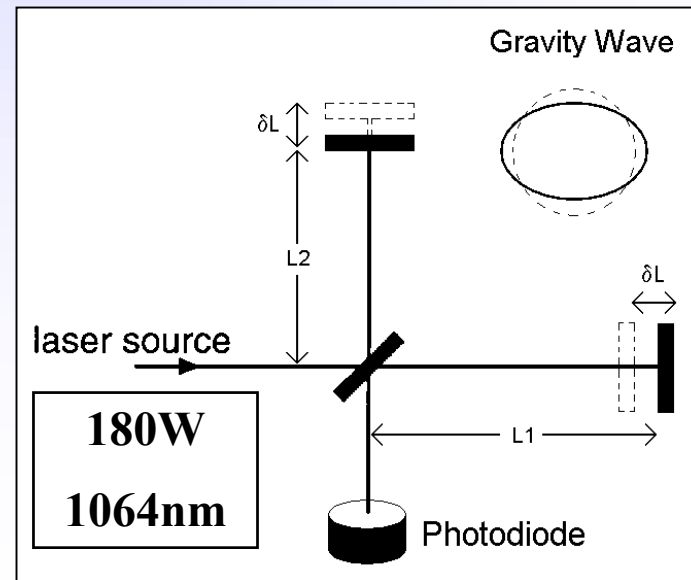
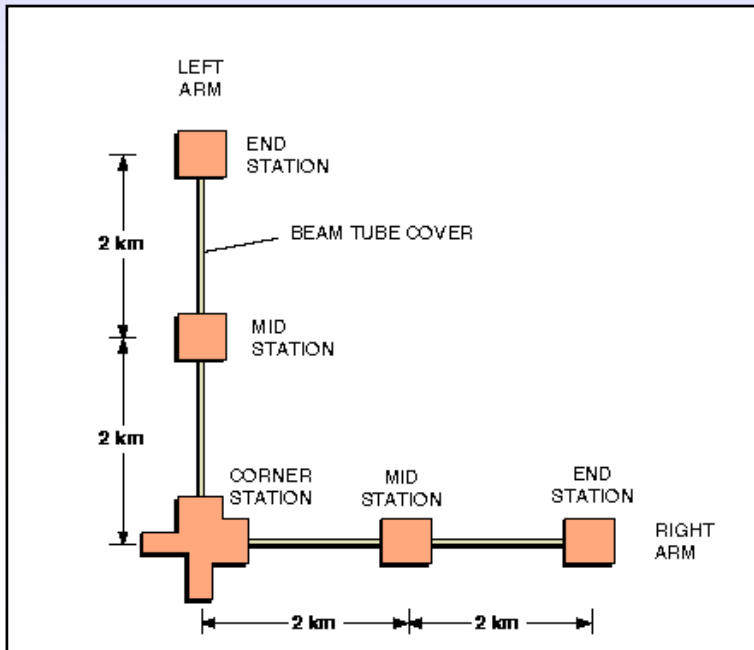
Predictions (I think we can do it...)



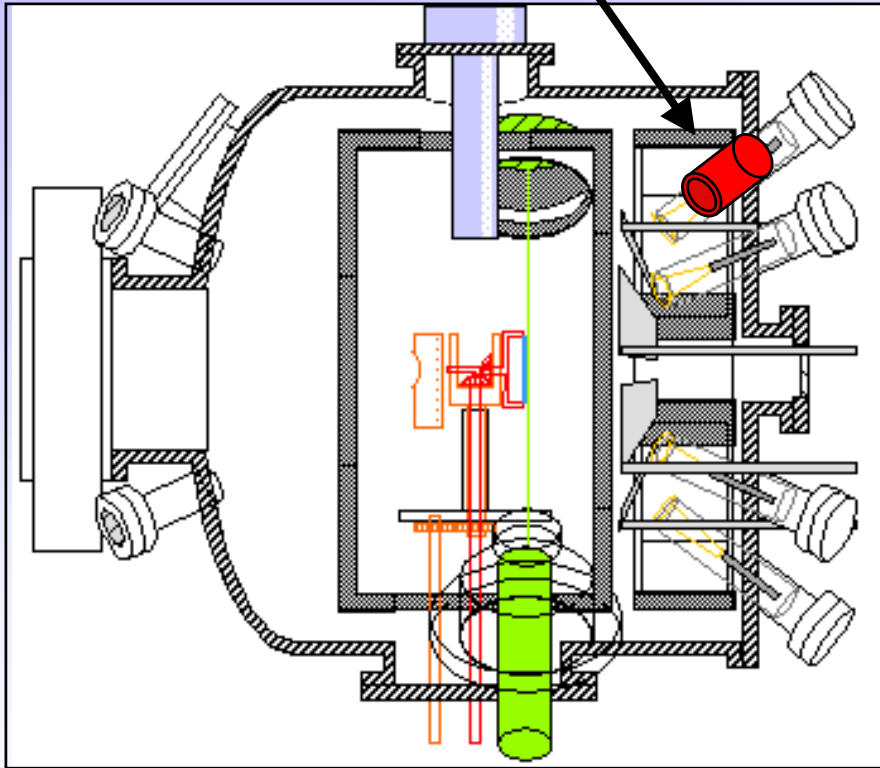
Detector	Power Stabilization	RF Detection	GW Channel
Diameter	4.5mm	1.5mm	1mm
Bias	-25V	-25V	-25V
Steady-State Power	1130mW	110mW	50mW
3-dB 1/RC Bandwidth	3MHz	30MHz (→ 180MHz)	60MHz
Quantum Efficiency	~ 90%	~ 90%	~ 90%

Laser Interferometer Gravitational Wave Observatory (LIGO)

Arm Length	4km
Beam Tube Diameter	4 ft.
Vacuum Pressure	$\sim 10^{-10}$ atm
Differential Strain	$\sim 10^{-18}$ m



N Plasma Source



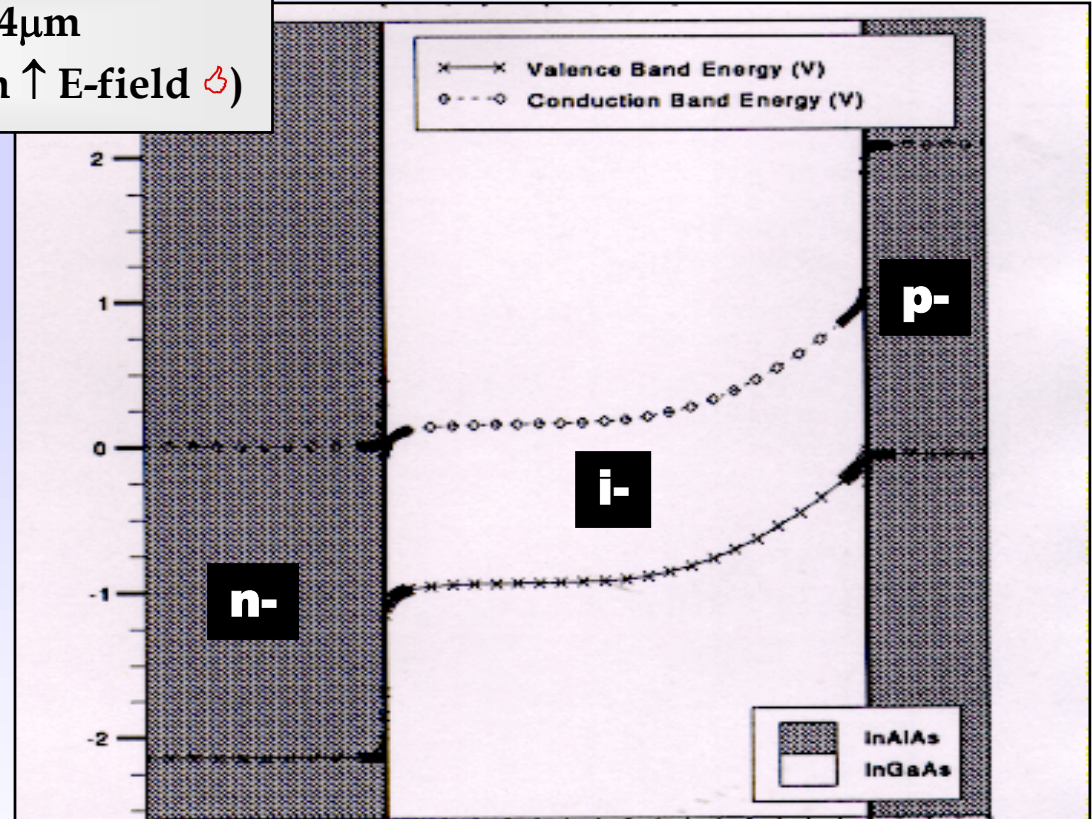
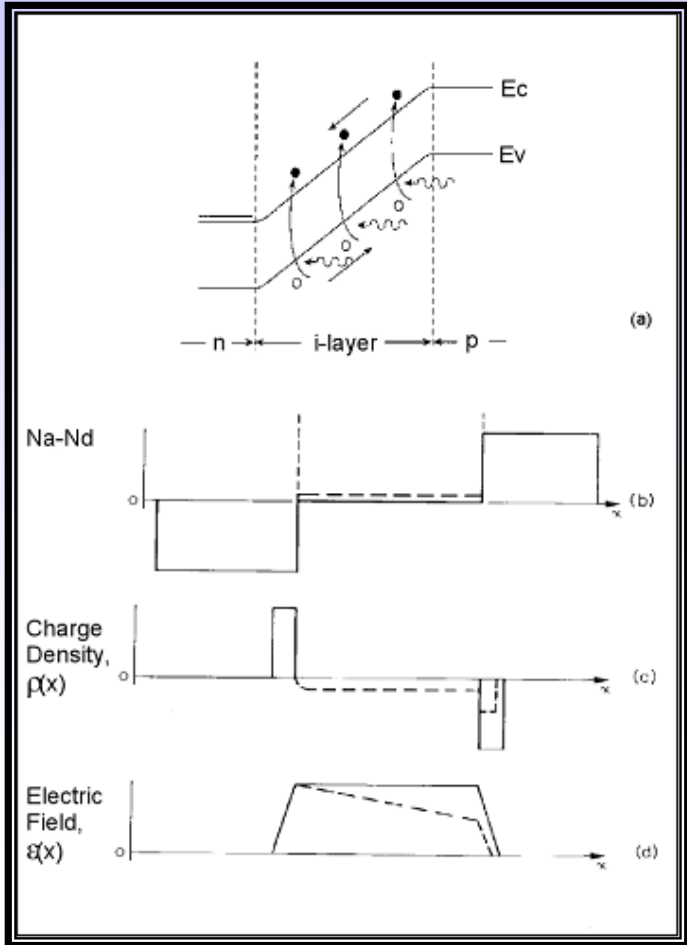
- Effusion cells for In, Ga, Al
- Cracking cell for As
- Abrupt interfaces
- Chamber is under UHV conditions to avoid incorporating contaminants
- RHEED can be used to analyze crystal growth *in situ* due to UHV environment
- $T=450-600^{\circ}\text{C}$

**Atomic source of nitrogen needed
→ Plasma Source!**

Heterojunction Band Gap Diagram



InAlAs and GaAs transparent at 1.064μm
 → Absorption occurs in I-region (in ↑ E-field ☺)

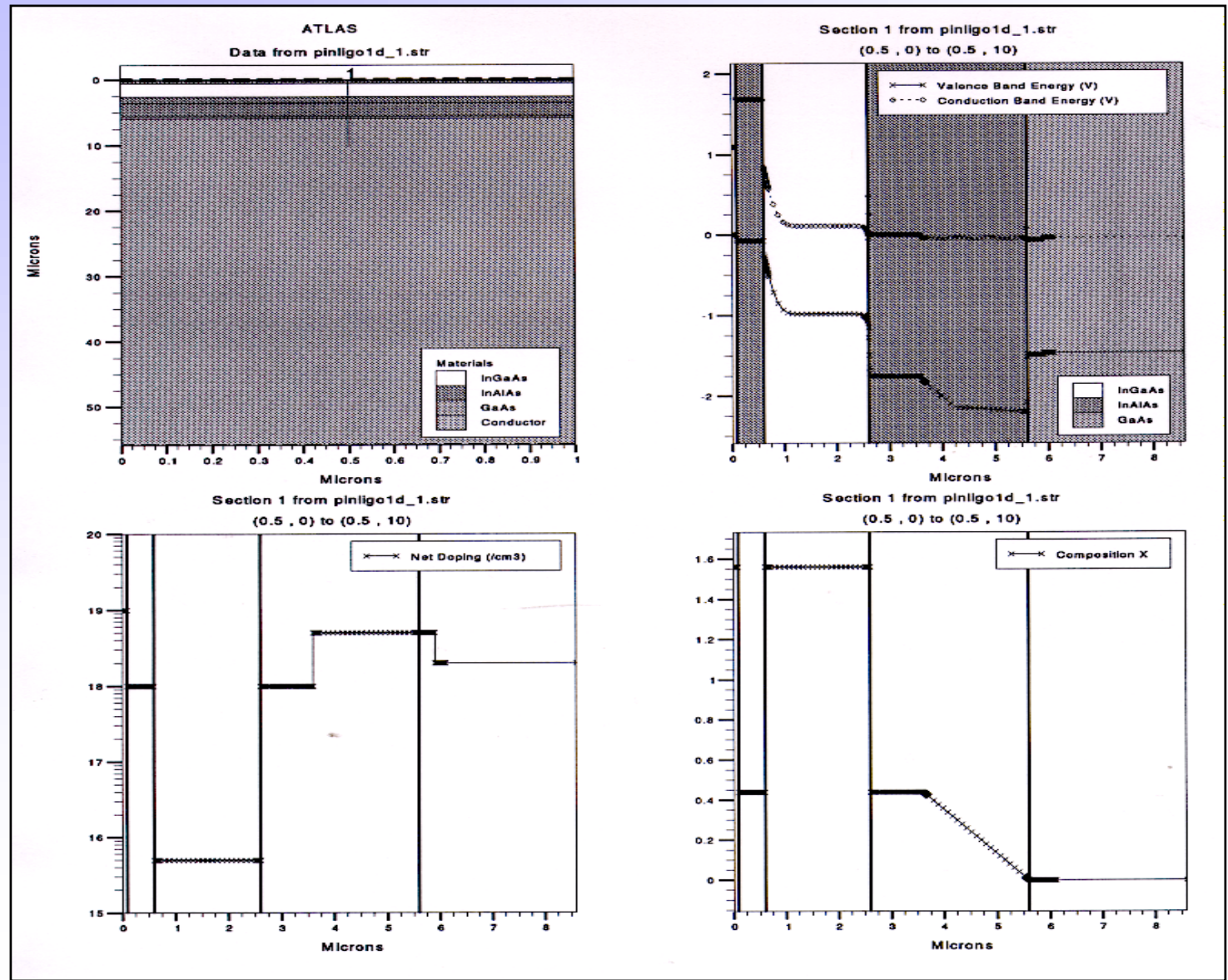


N-layer:
 $\text{In}_{.25}\text{Al}_{.75}\text{As}$
 or GaAs
 $E_{g2} = 2.0 - 1.4\text{eV}$

I-layer:
 $\text{In}_{.25}\text{Ga}_{.75}\text{As}$, or
 $\text{Ga}_{.88}\text{In}_{.12}\text{N}_{.01}\text{As}_{.99}$
 $E_{g1} = 1.1\text{eV}$

P-layer:
 $\text{In}_{.25}\text{Al}_{.75}\text{As}$
 or GaAs
 $E_{g2} = 2.0 - 1.4\text{eV}$

Full Structure Simulated by ATLAS

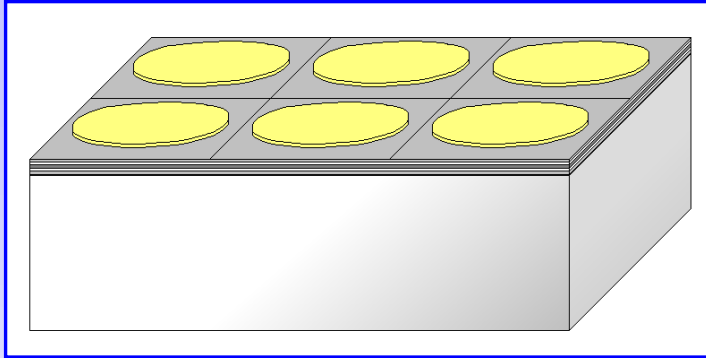


High Efficiency Detector Process (1)

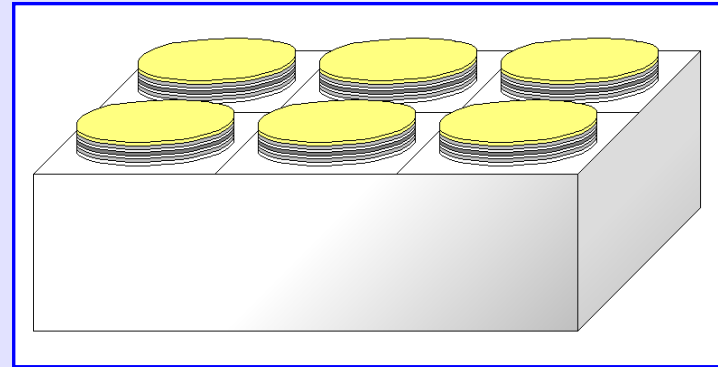


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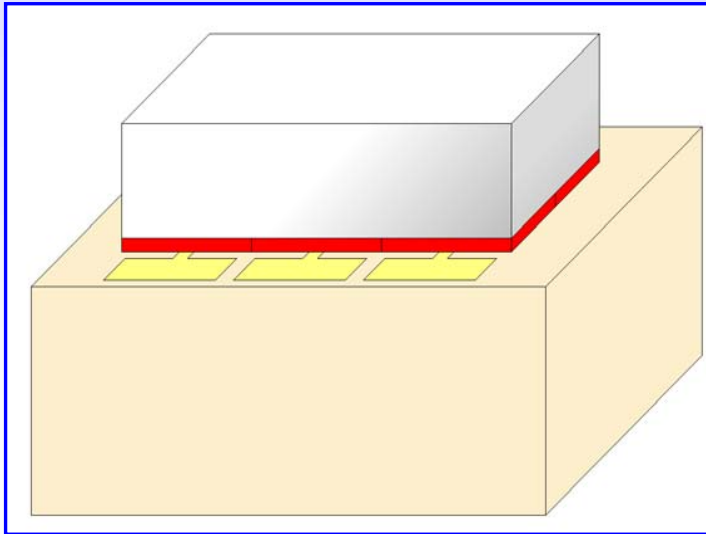
1. Deposit and Pattern P-Contact



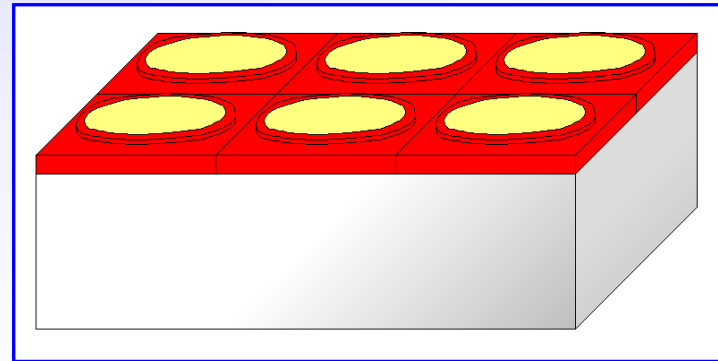
2. Etch Mesa - $H_2SO_4:H_2O_2:H_2O$ and Passivate in $(NH_4)_2S+$



4. Flip-Chip Bond



3. Encapsulate Exposed Junction



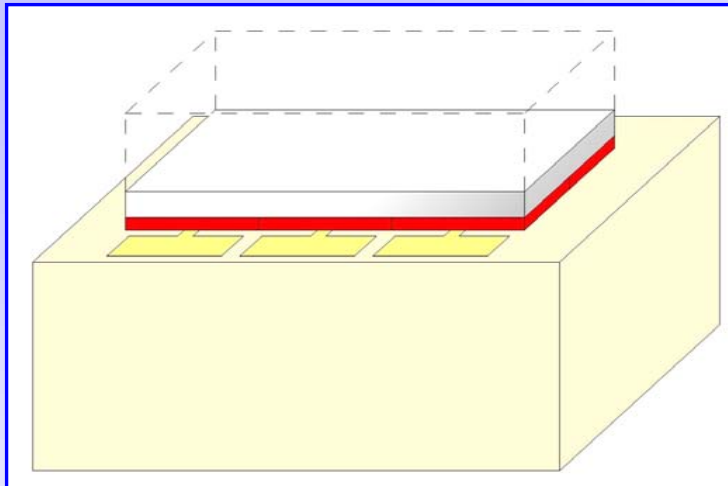
	- N+ GaAs Substrate		- Epitaxial Layers		- Au Contacts		- Polyimide Insulator		- SiN_x AR Coating		- AlN Ceramic
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High Efficiency Detector Process (2)

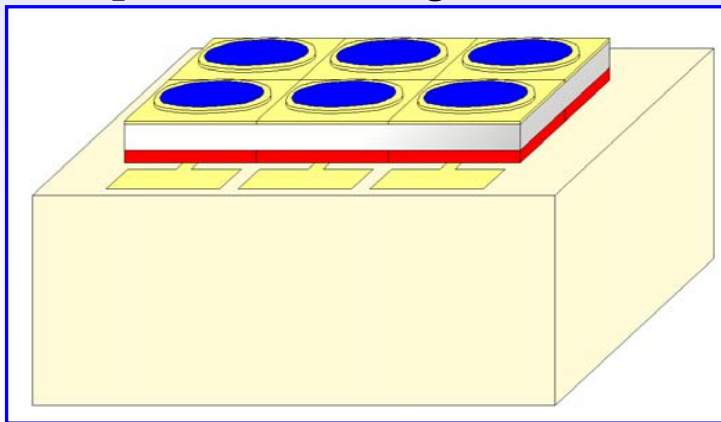


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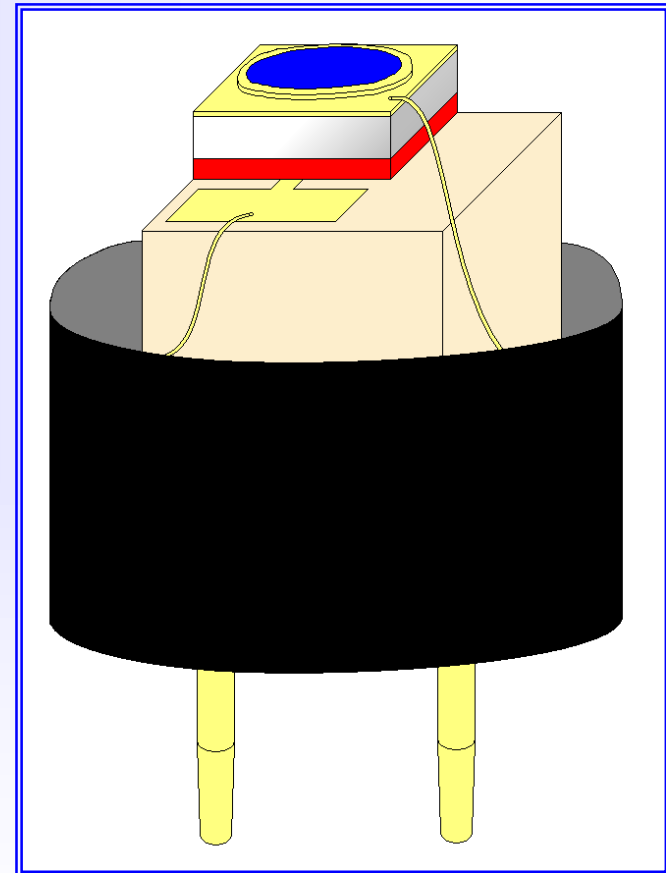
5. Thin N+ GaAs Substrate



6. Deposit AR Coating & N-Contact

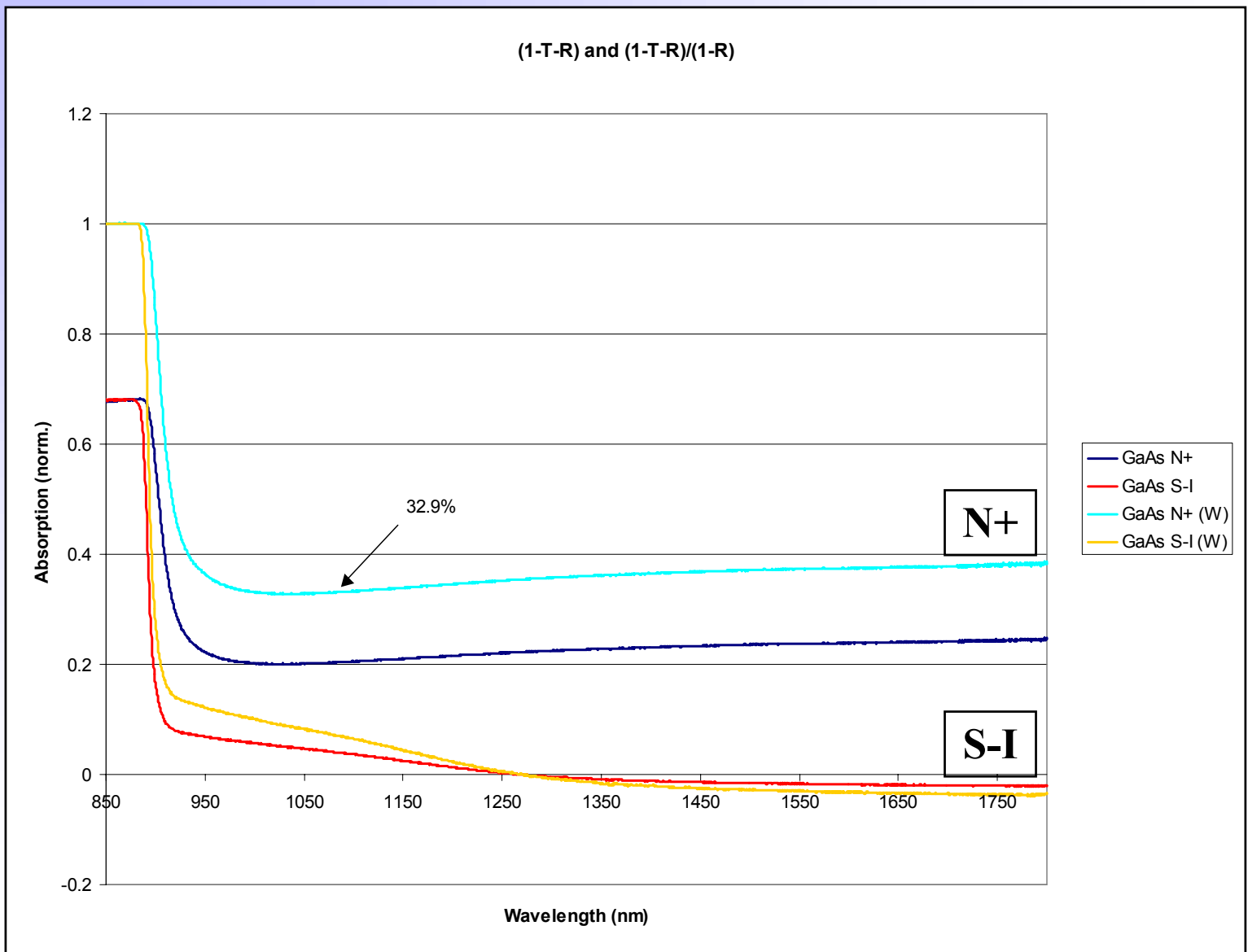


7. Saw, Package and Wire-Bond

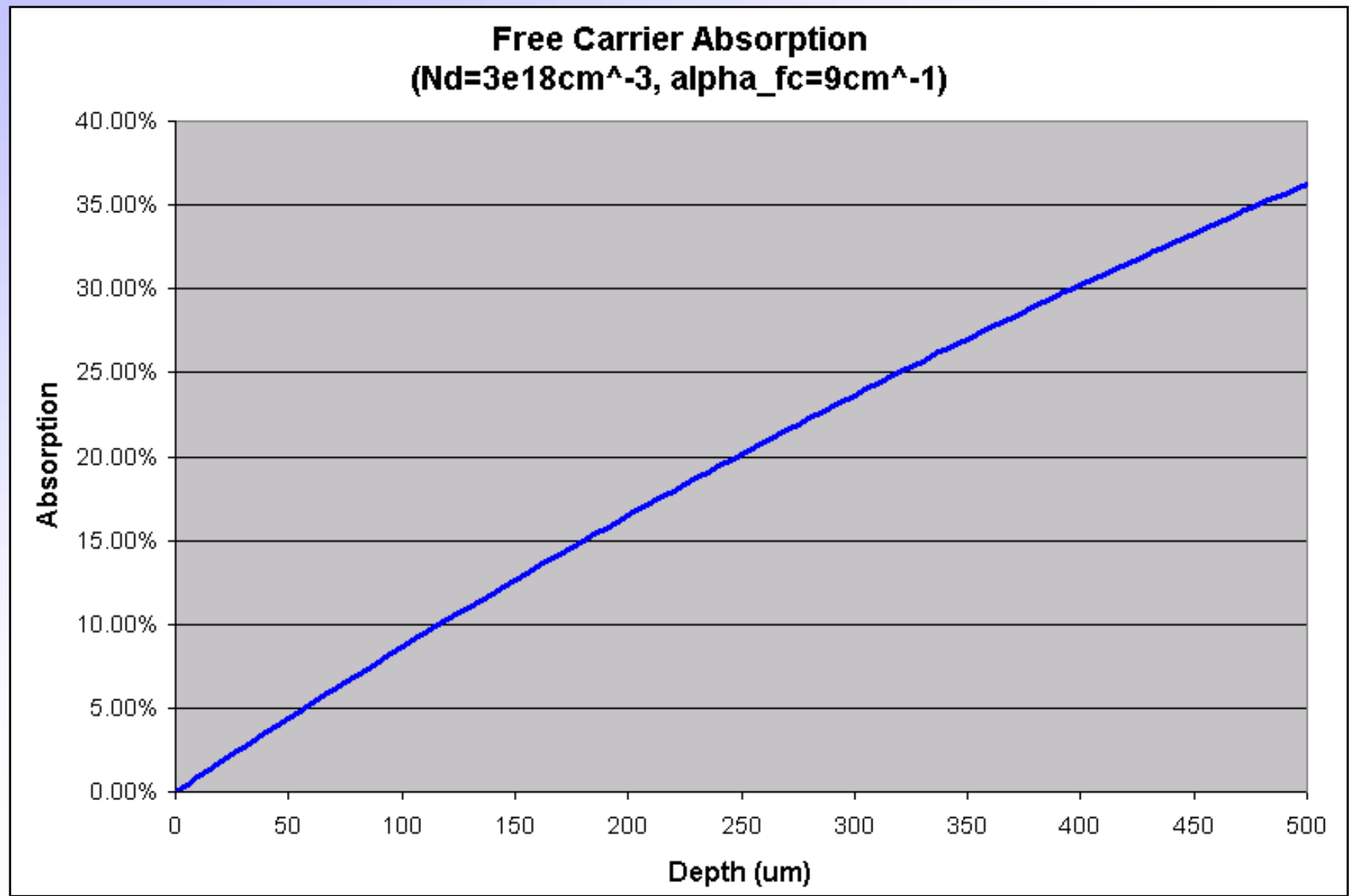


 - N+ GaAs Substrate	 - Epitaxial Layers	 - Au Contacts	 - Polyimide Insulator	 - SiN _x AR Coating	 - AlN Ceramic
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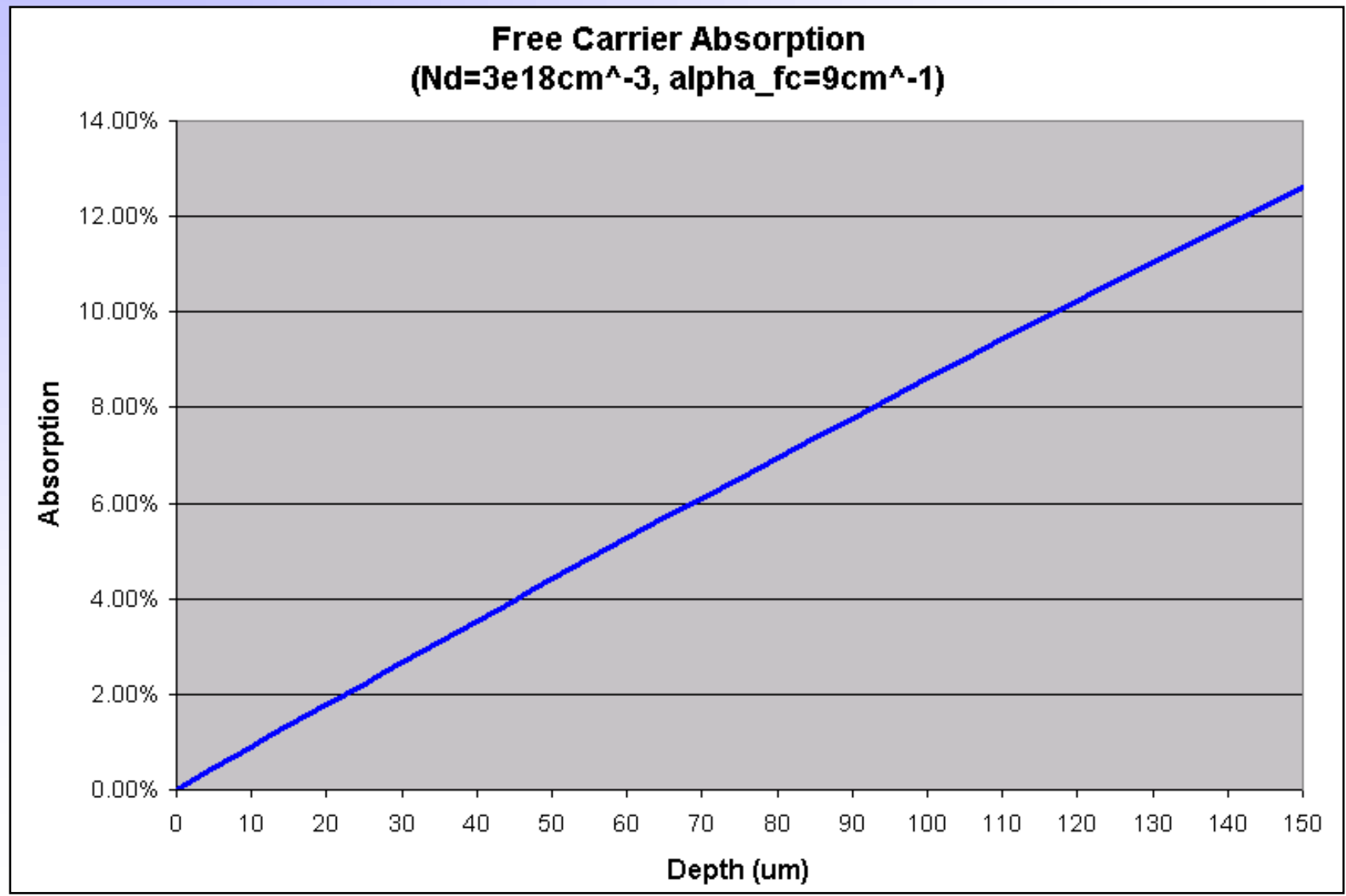
Free-Carrier Absorption



Free-Carrier Absorption



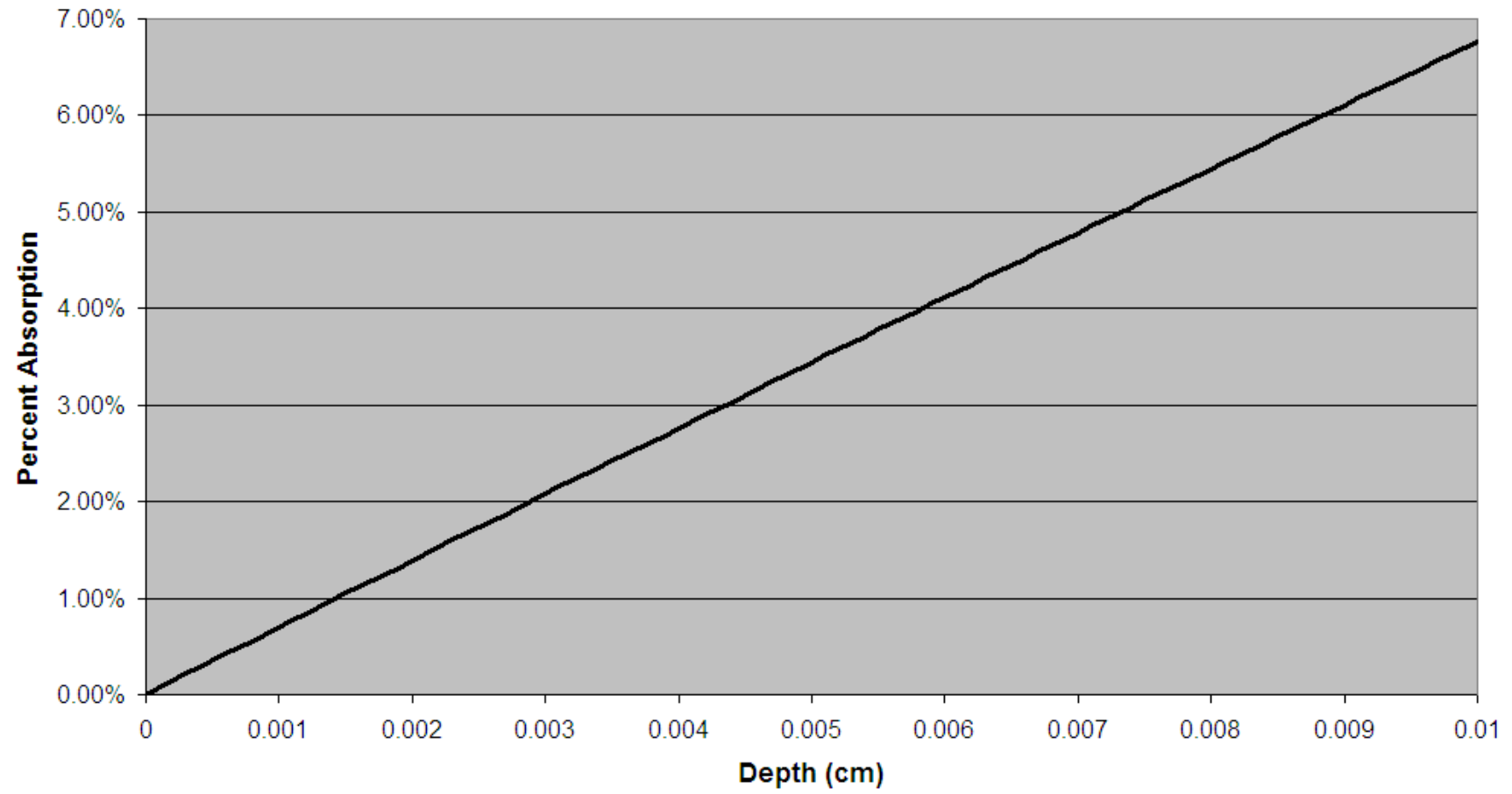
Free-Carrier Absorption



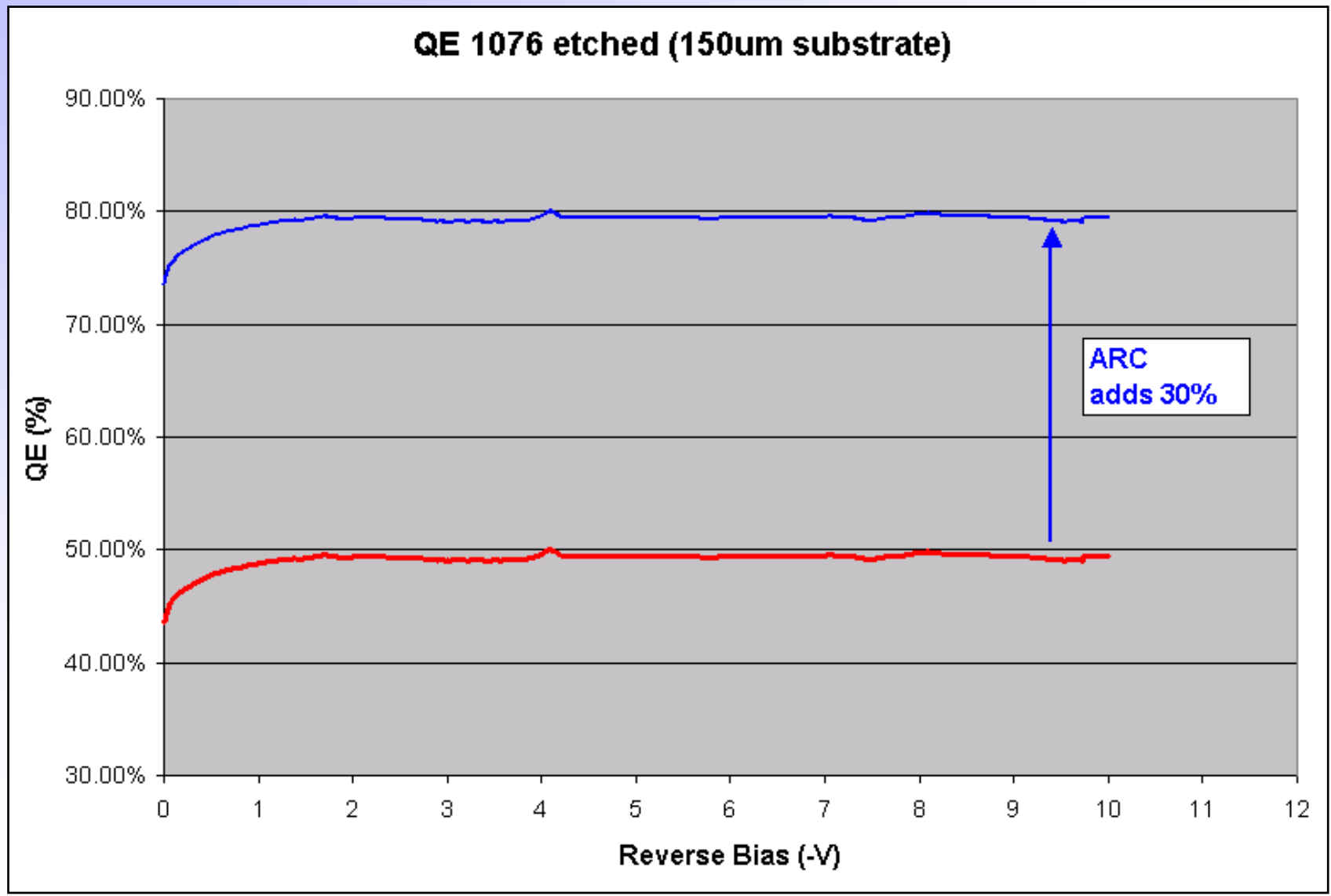
Free-Carrier Absorption $5e17\text{cm}^{-3}$



$N_d = 5e17\text{cm}^{-3}$, $\alpha_{fc} = 7\text{cm}^{-1}$



Thinned Device QE (w/ ARC)

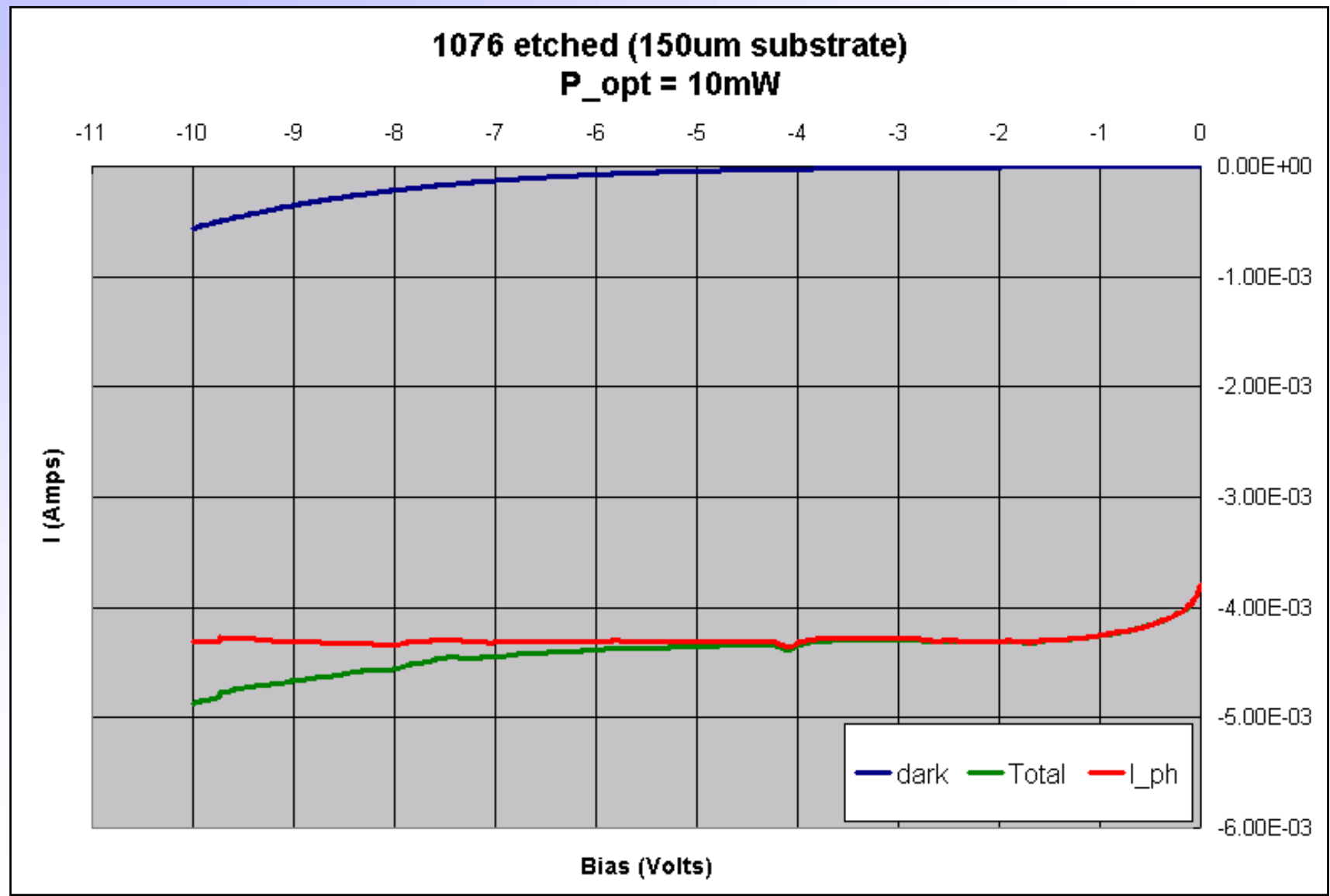


Photodiode Specifications



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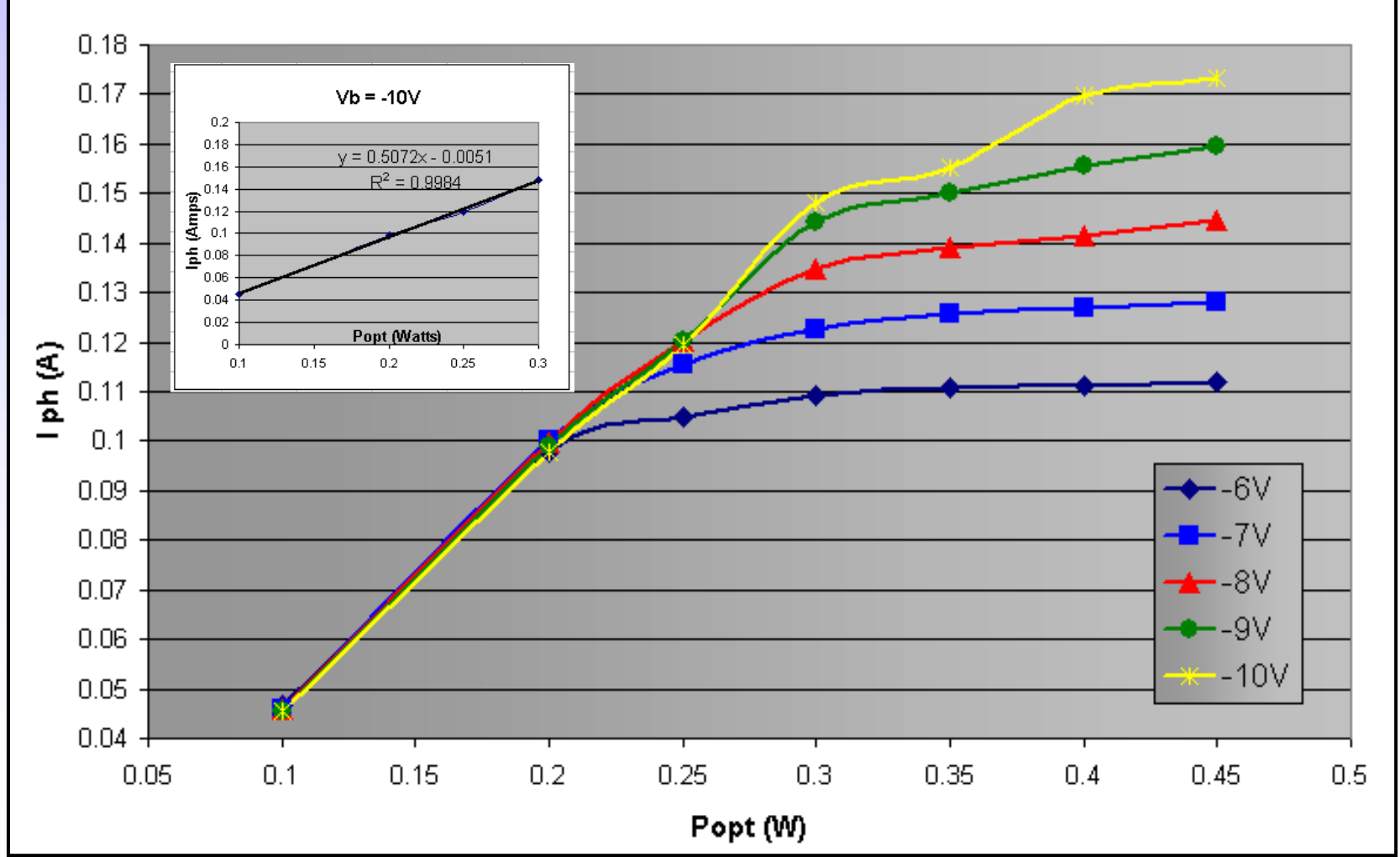
Thinned Device Photocurrent



DC Device Response



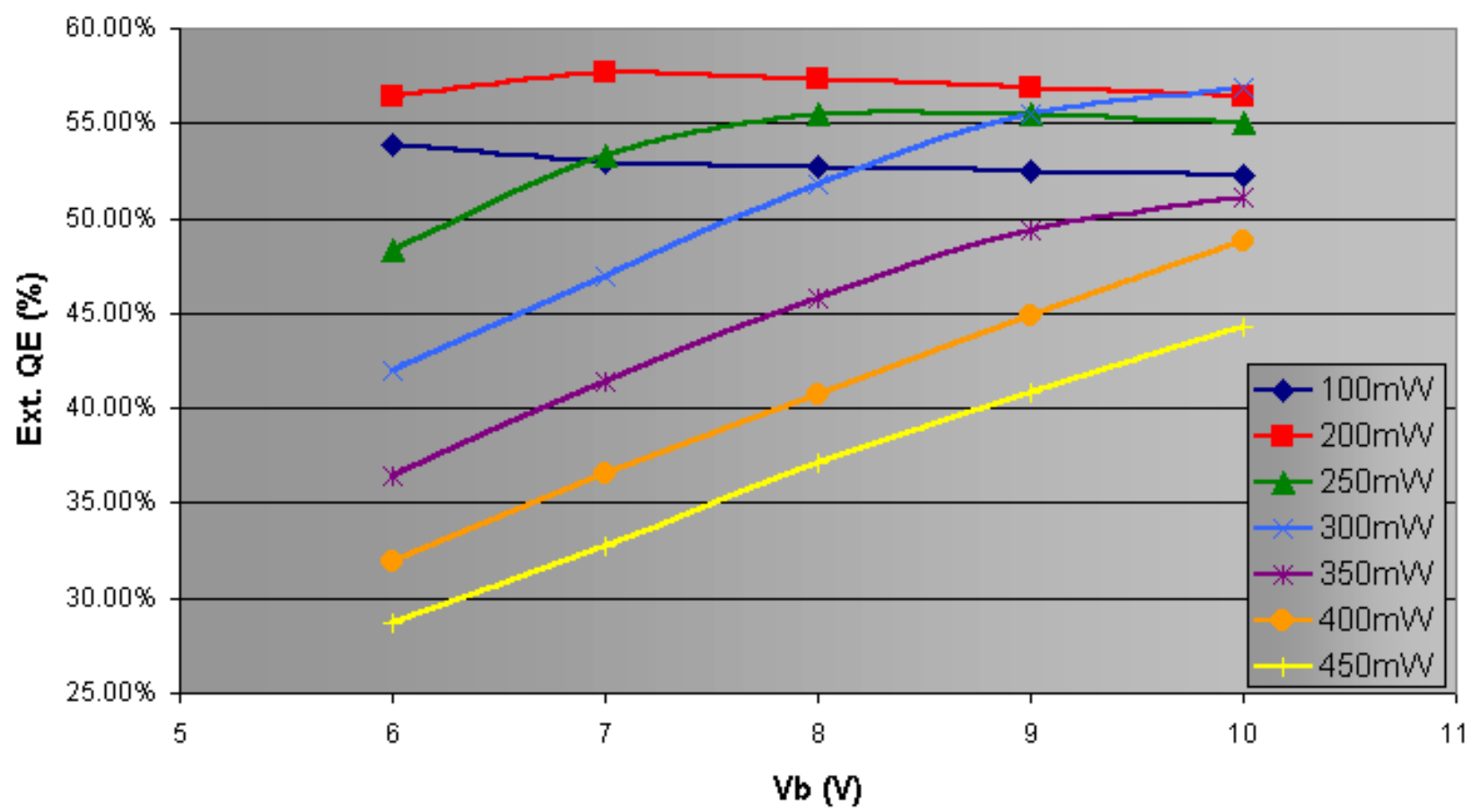
Photocurrent vs. Optical Power vs. Bias InGaAs Device



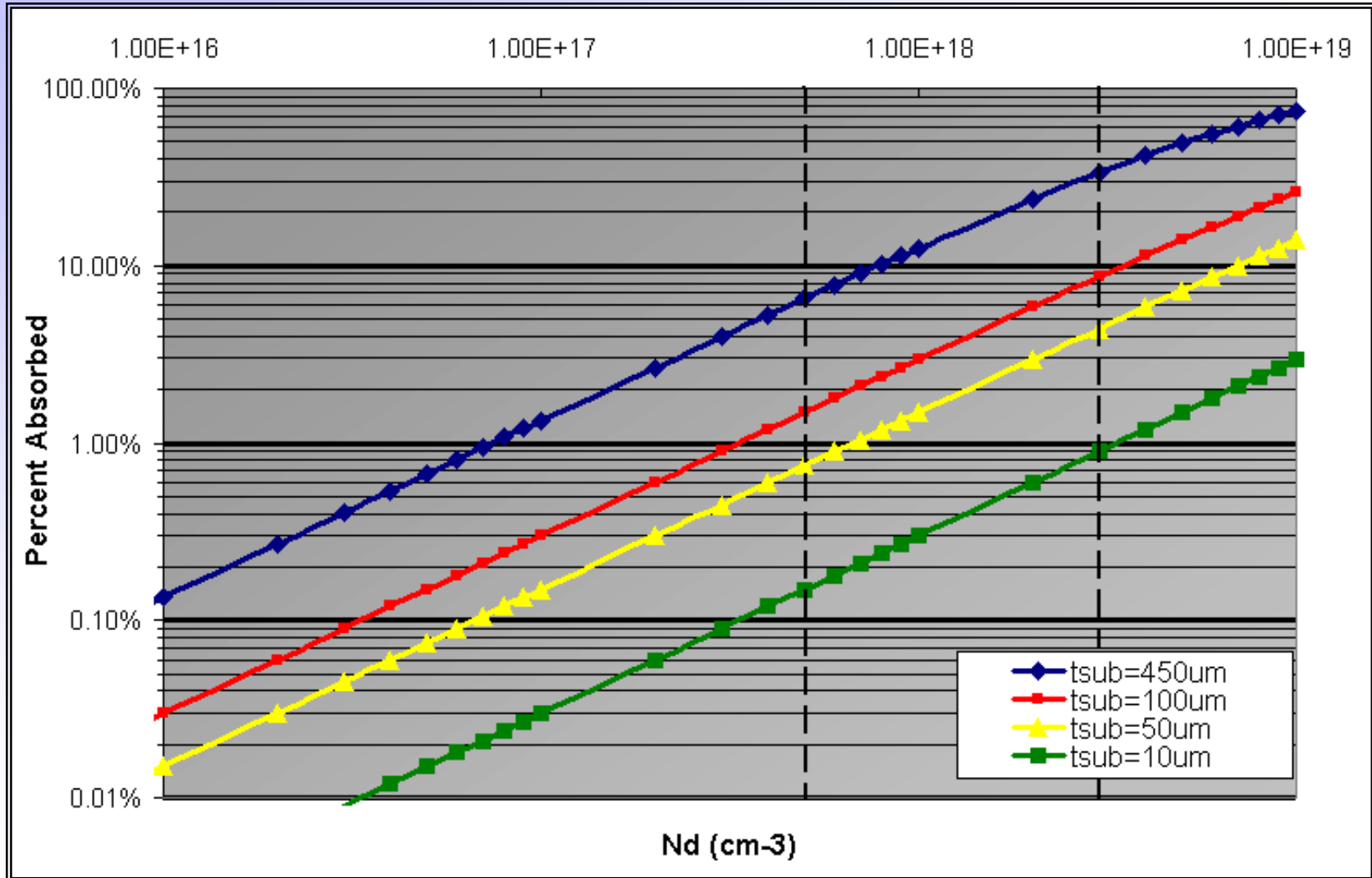
DC Device Efficiency



Quantum Efficiency vs. Bias vs. Optical Power Unfocused Beam, InGaAs Device



Free-Carrier Absorption

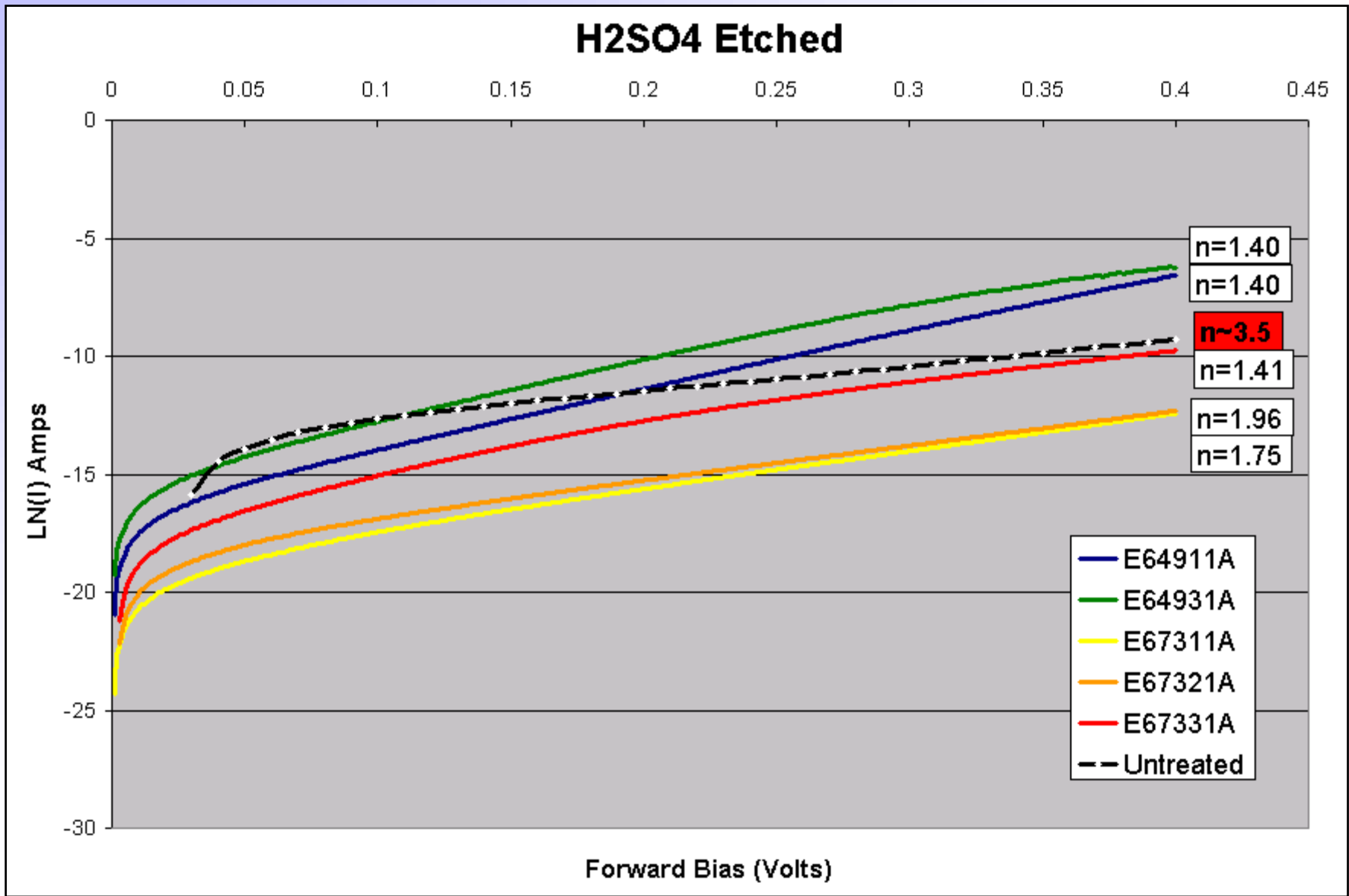


$$A = 1 - \exp(-t_{sub} \cdot \alpha_{fc}), \quad \alpha_{fc} = N_d * 3e-18$$

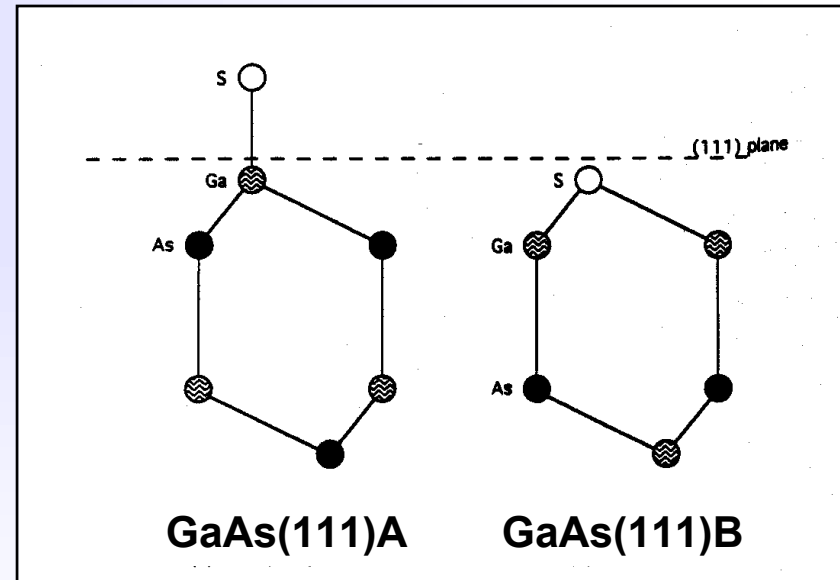
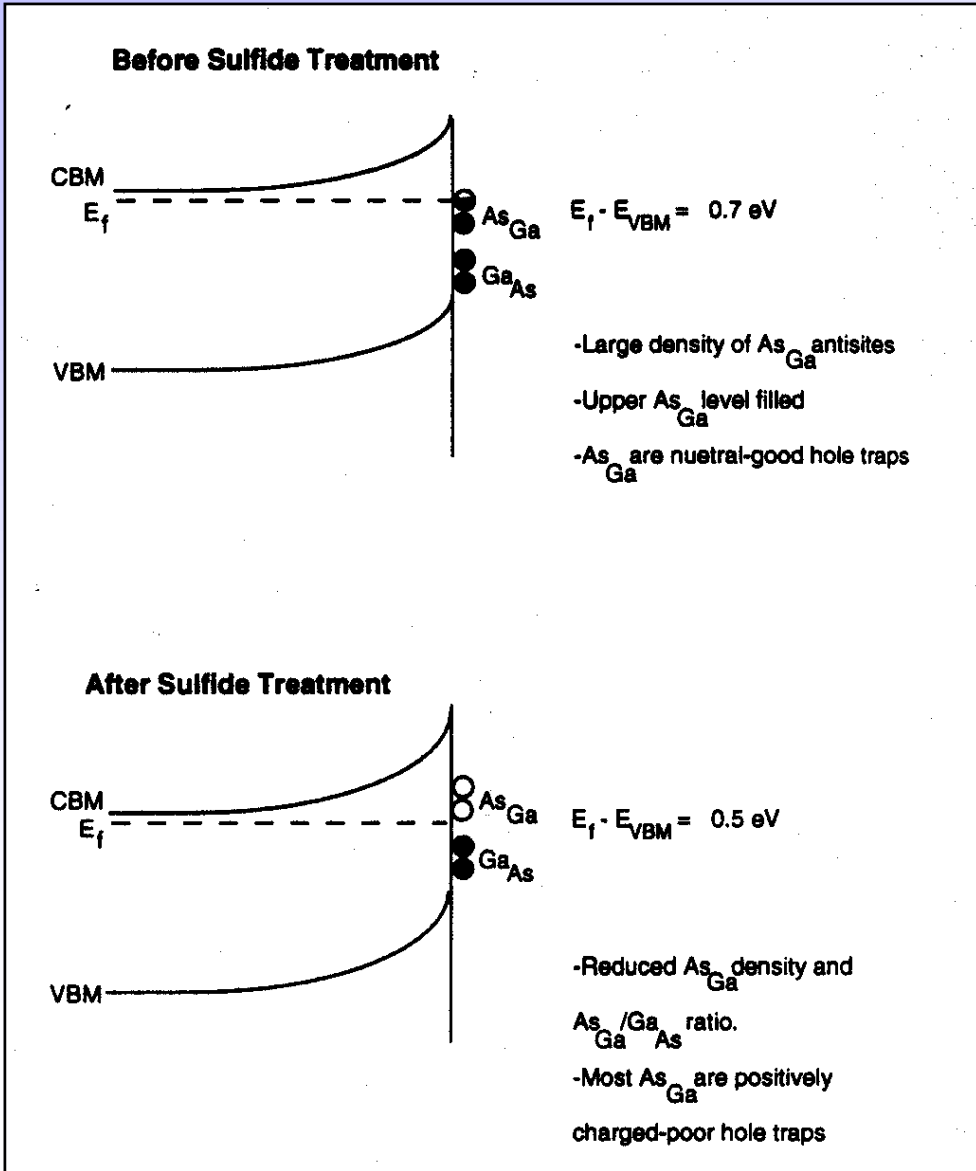
Surface Passivation Results (2)



H2SO4 Etched

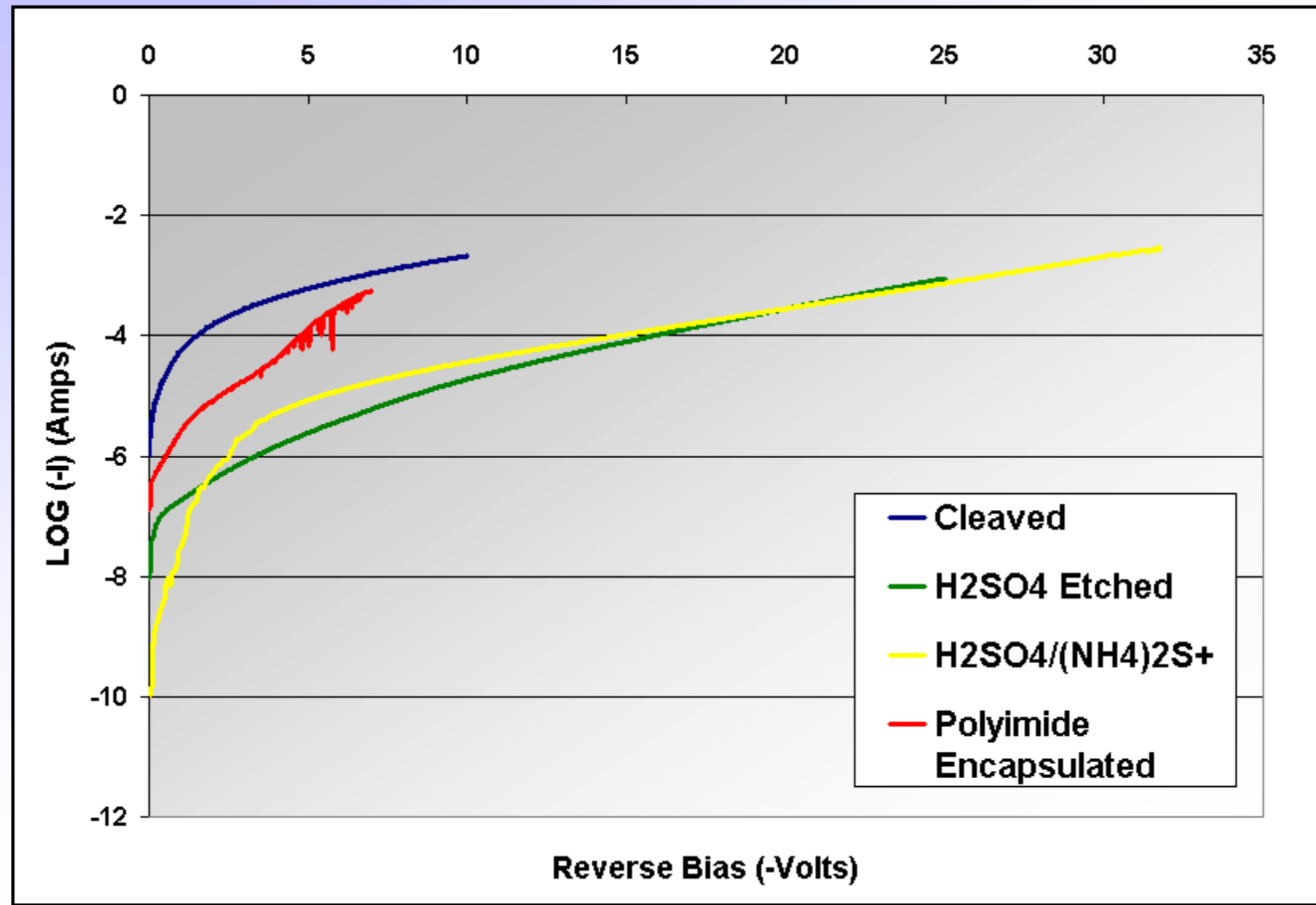


$(\text{NH}_4)_2\text{S}$ Surface States

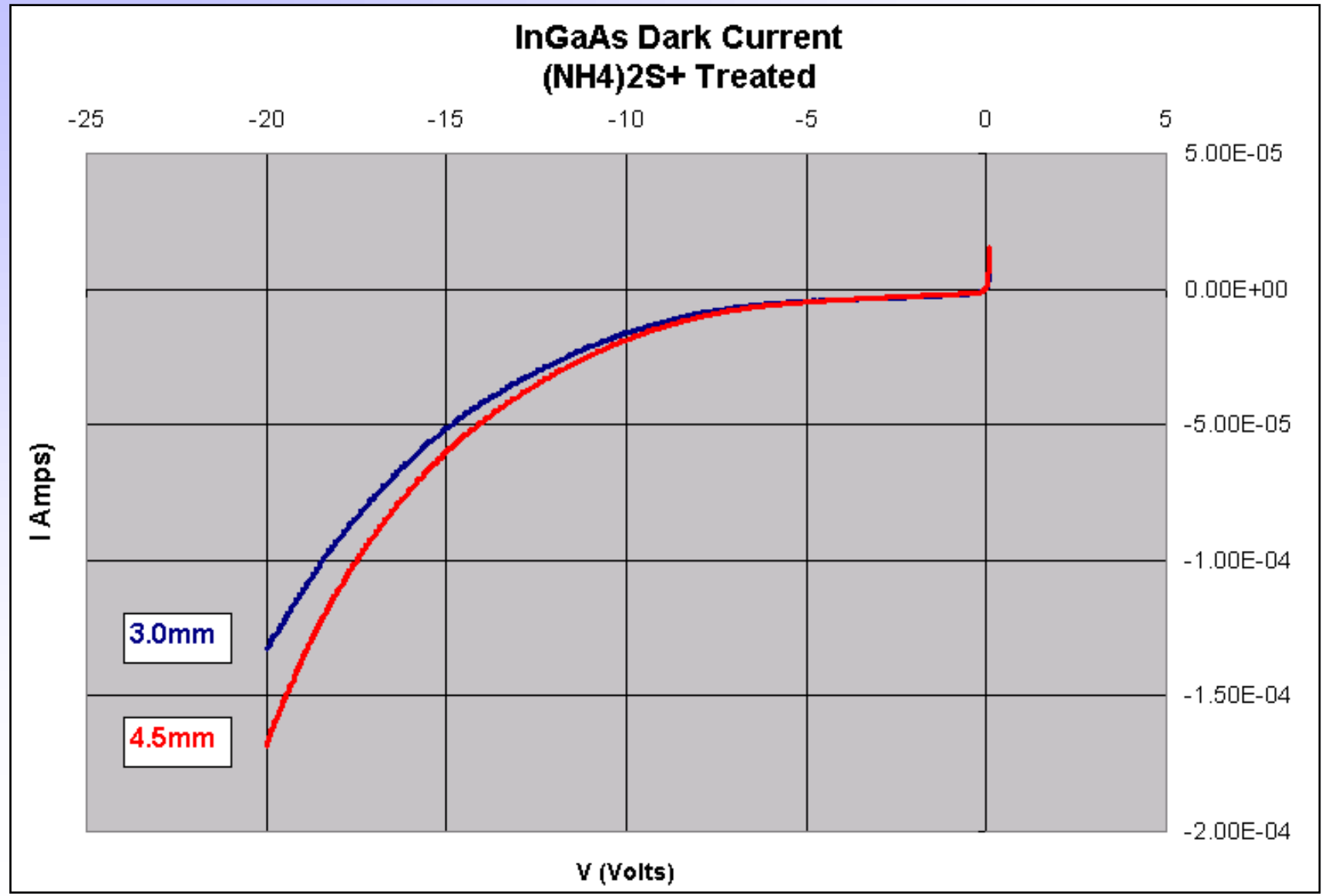


(Green and Spicer, 1993)

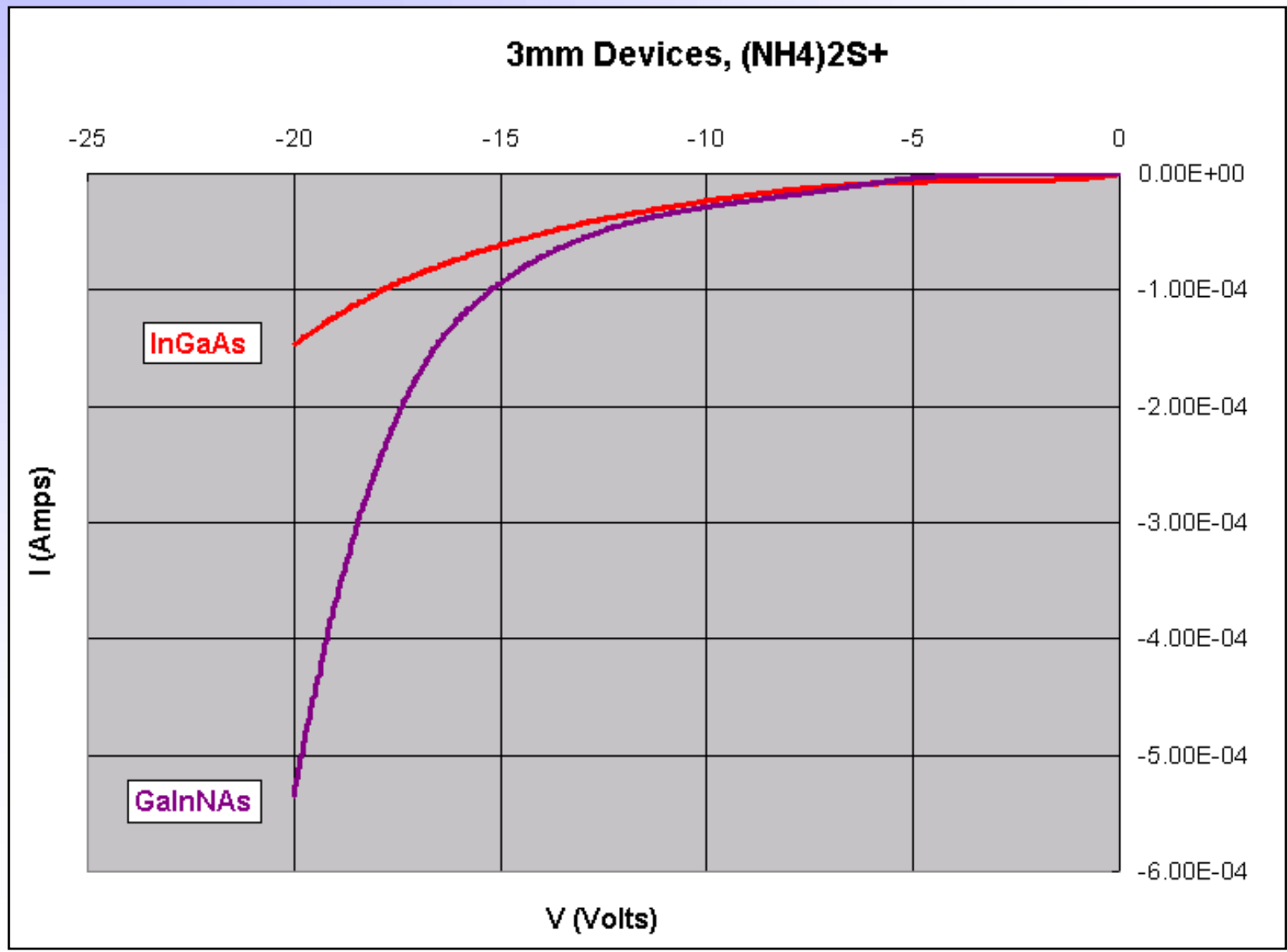
Surface Passivation Results



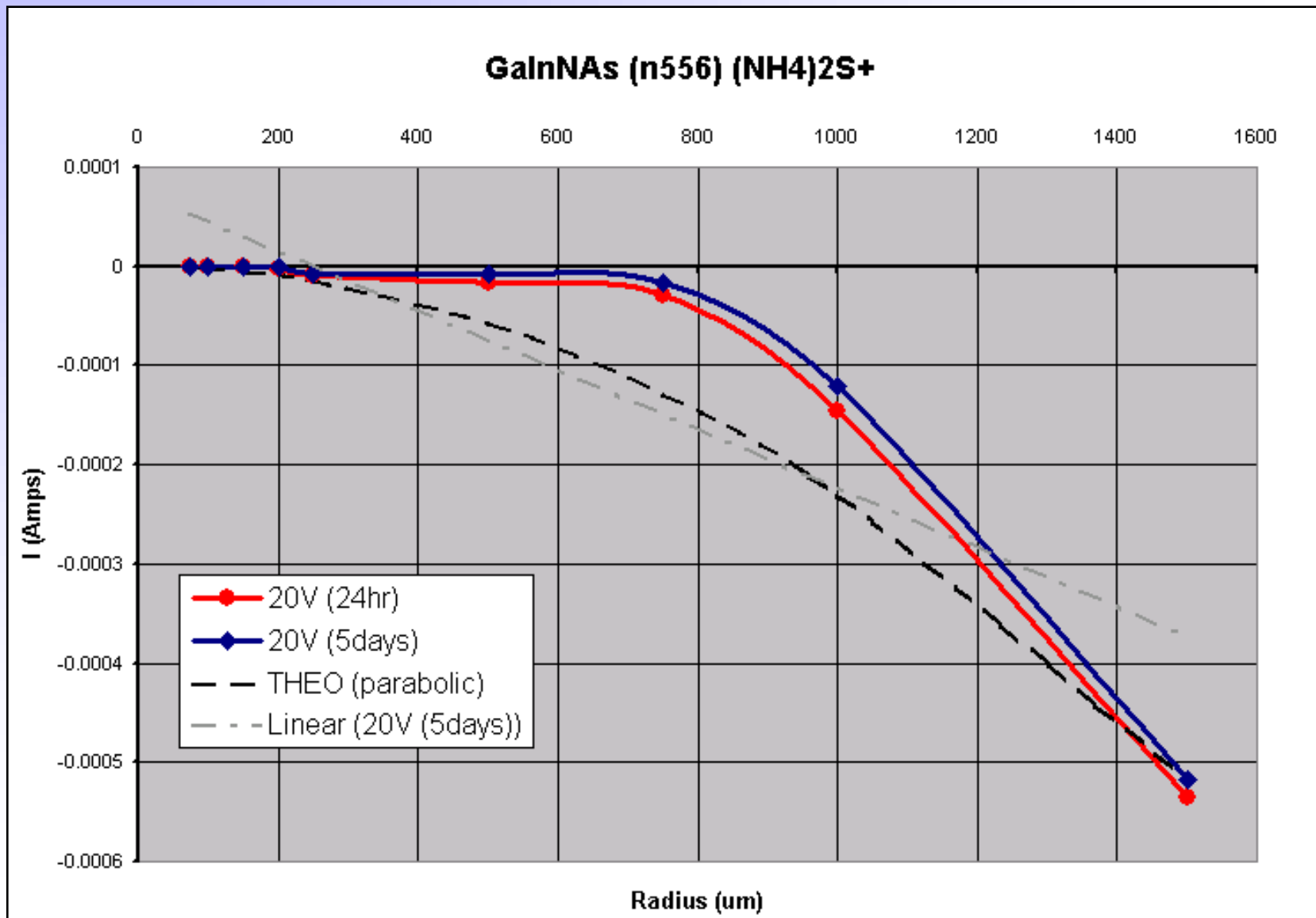
Large InGaAs Devices, -20V Bias



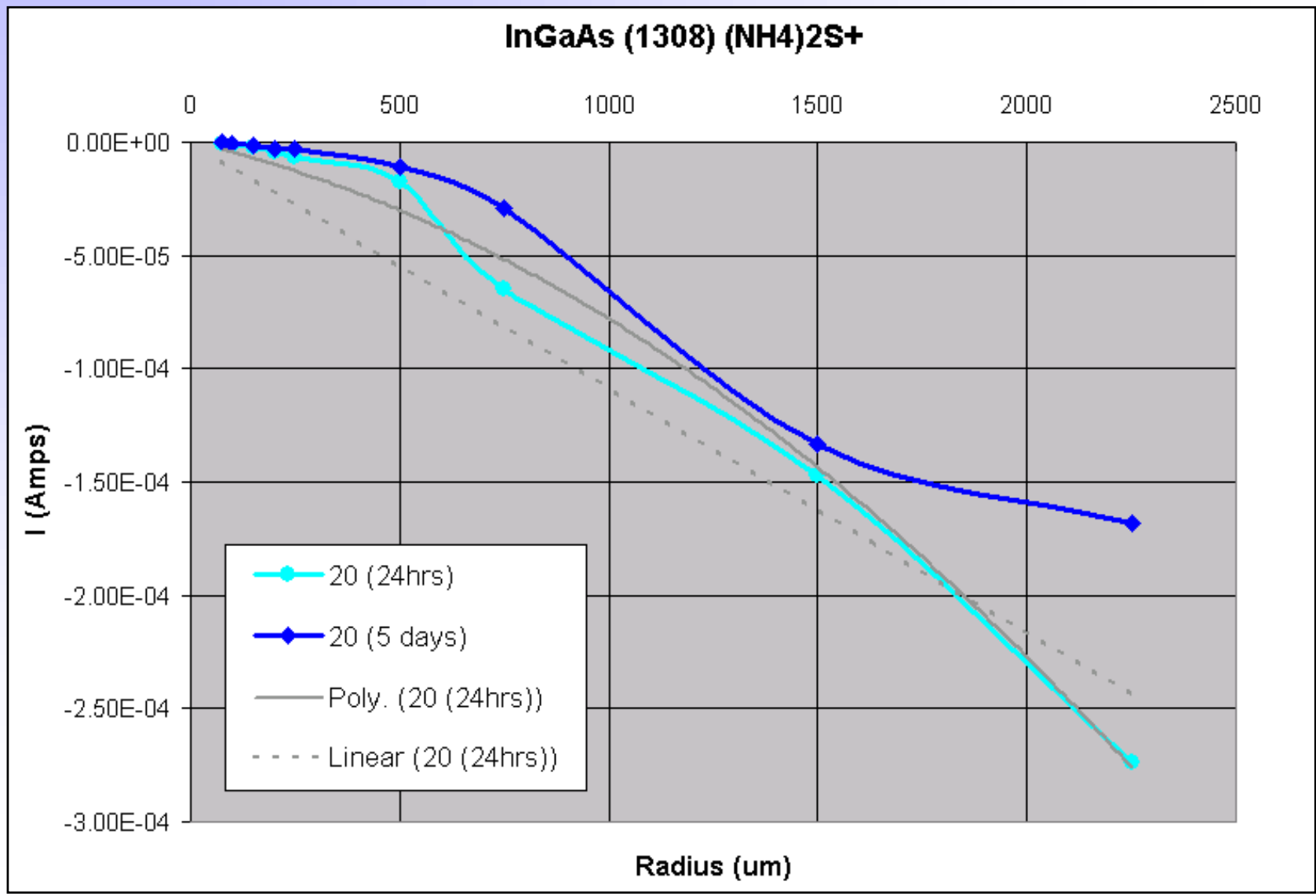
InGaAs vs. GaInNAs Dark Current



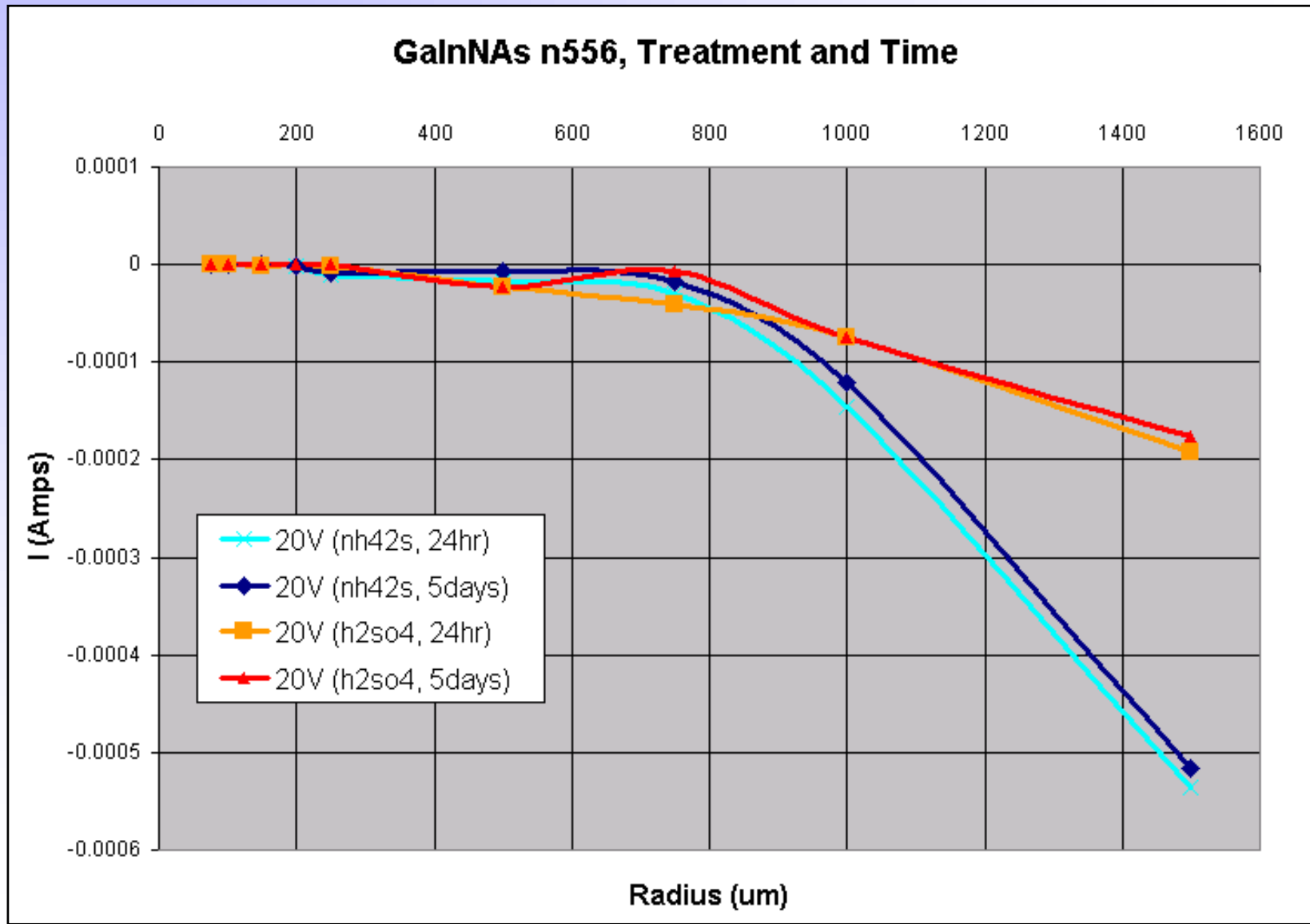
GalNAs Dark Current



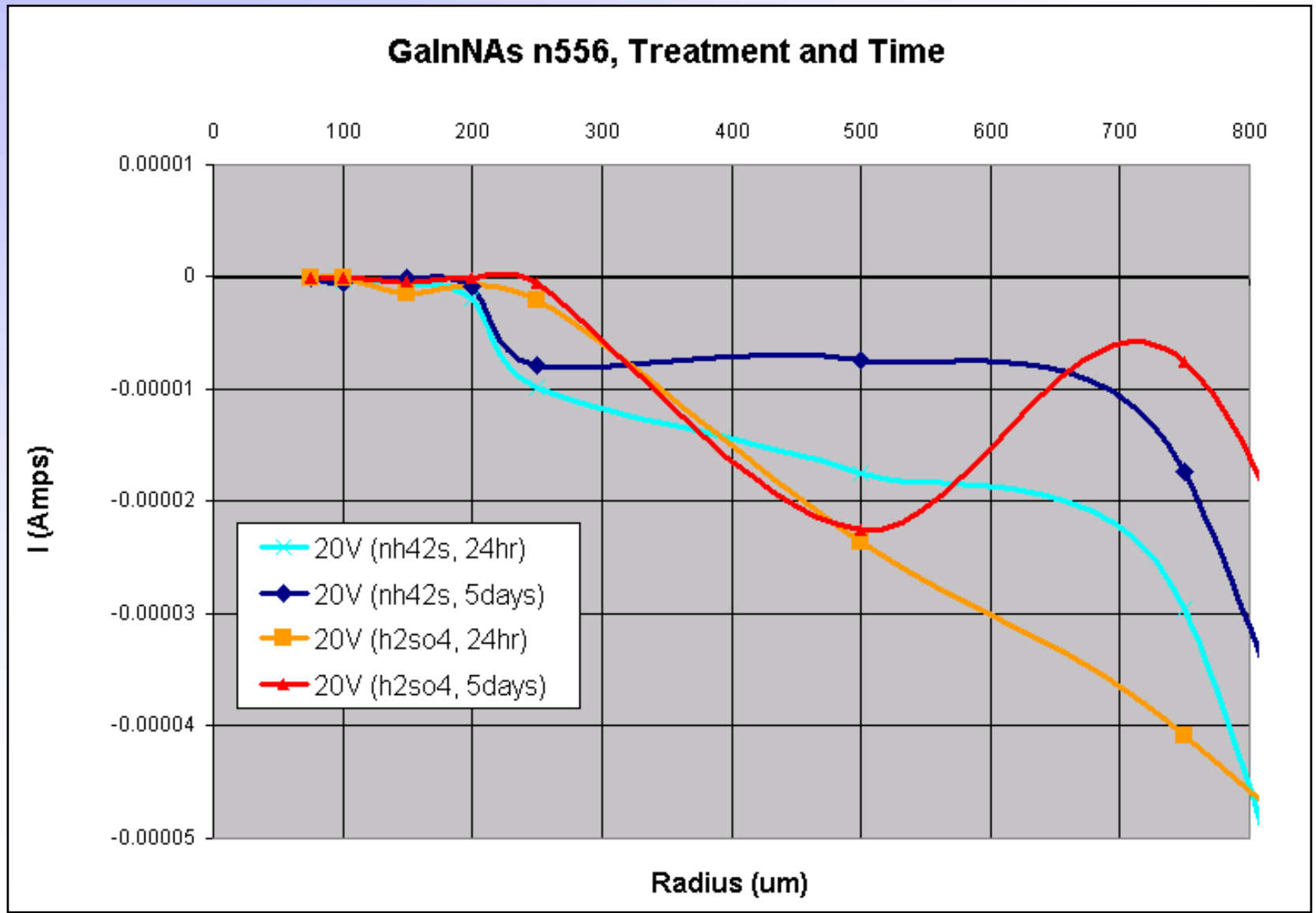
InGaAs Dark Current



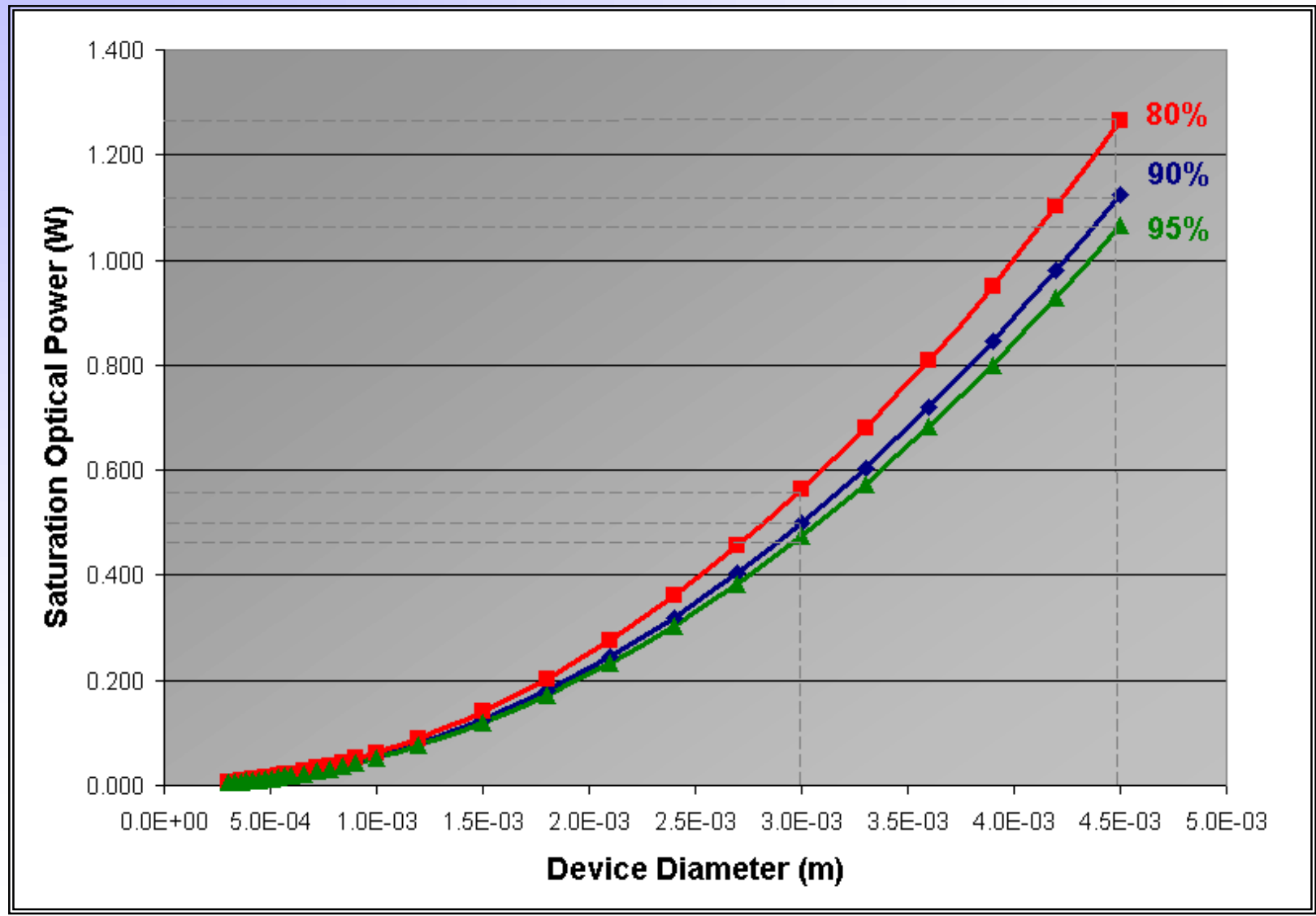
GalInNAs H2SO4 vs. (NH4)2S+



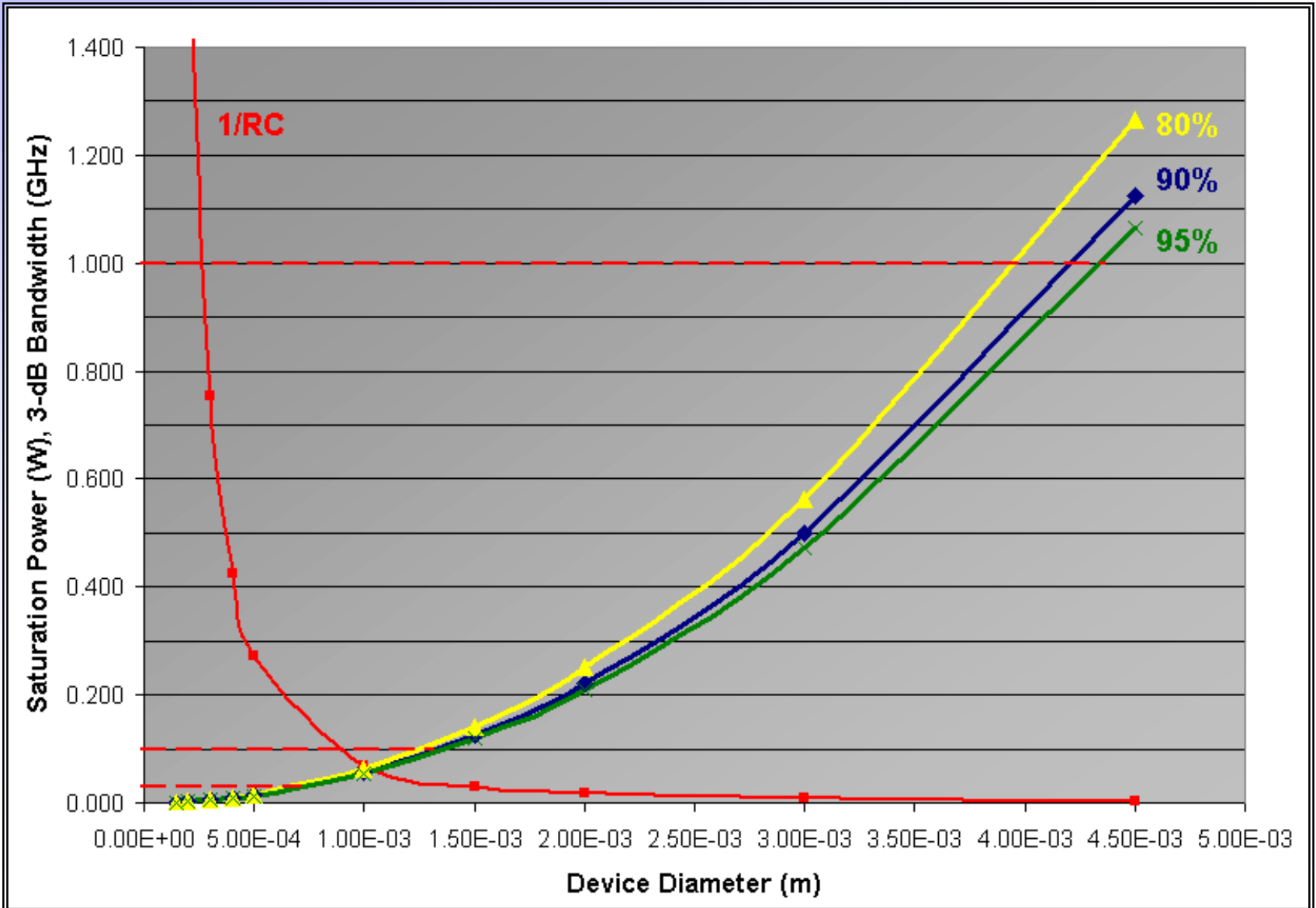
GalNAs H2SO4 vs. (NH4)2S+



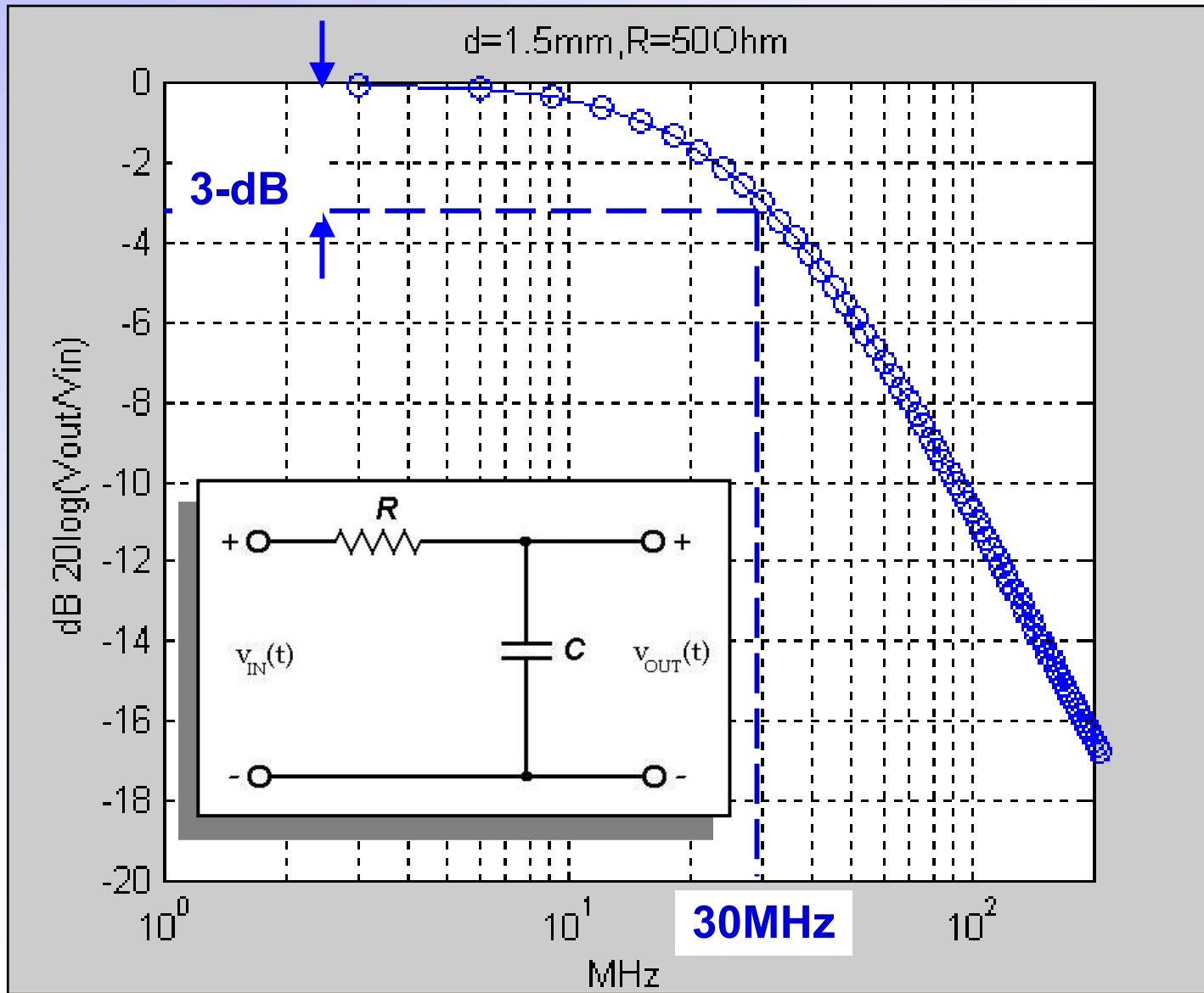
Theoretical Saturation Powers



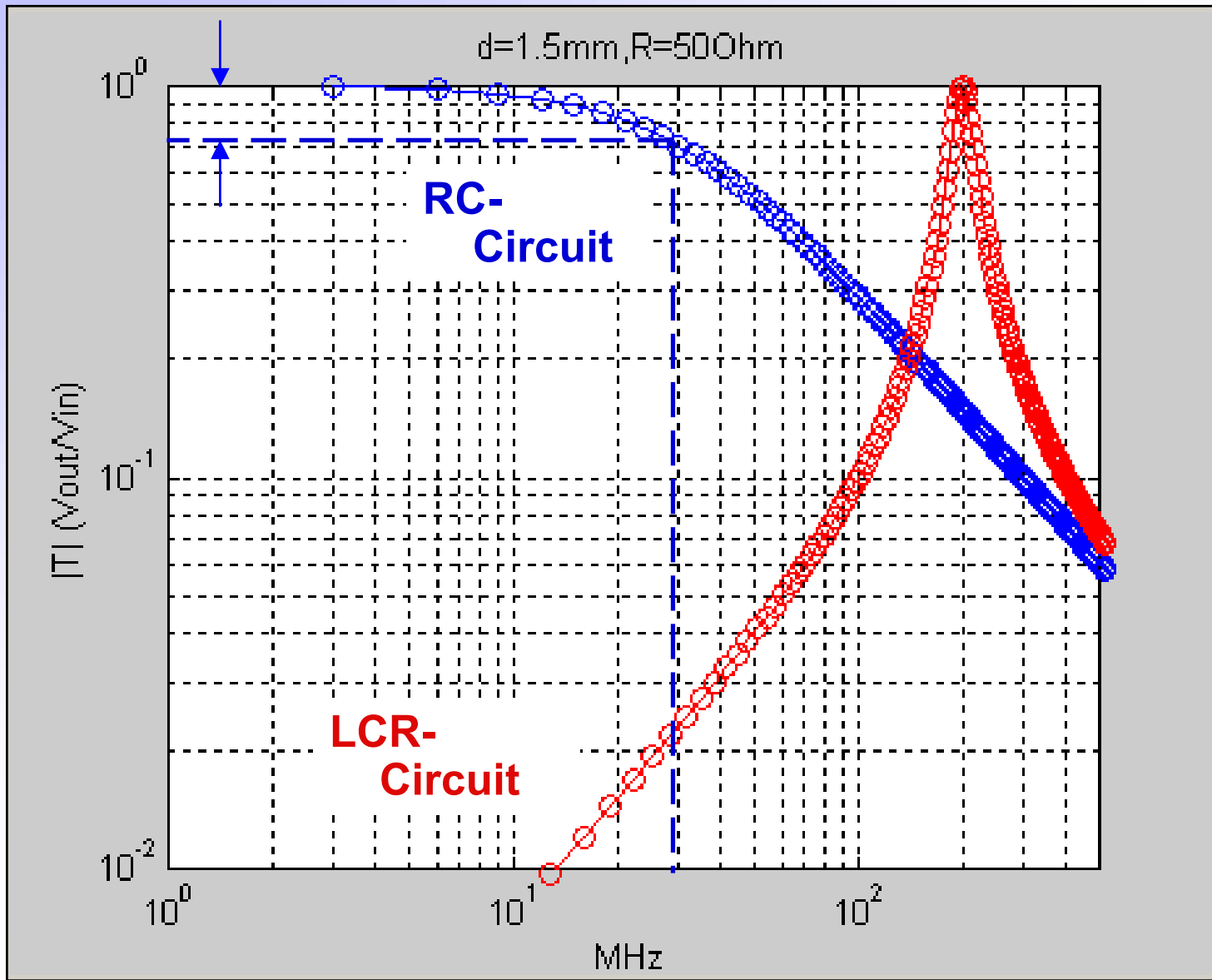
Theoretical Saturation Powers



RC-Circuit Bode Plot



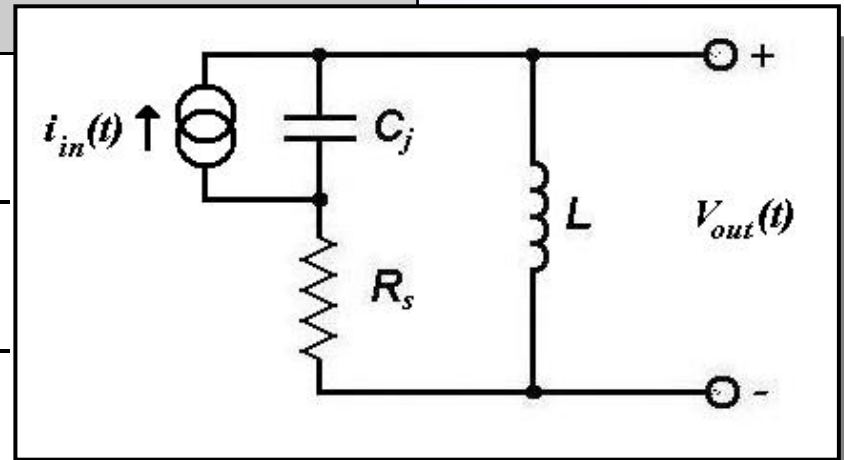
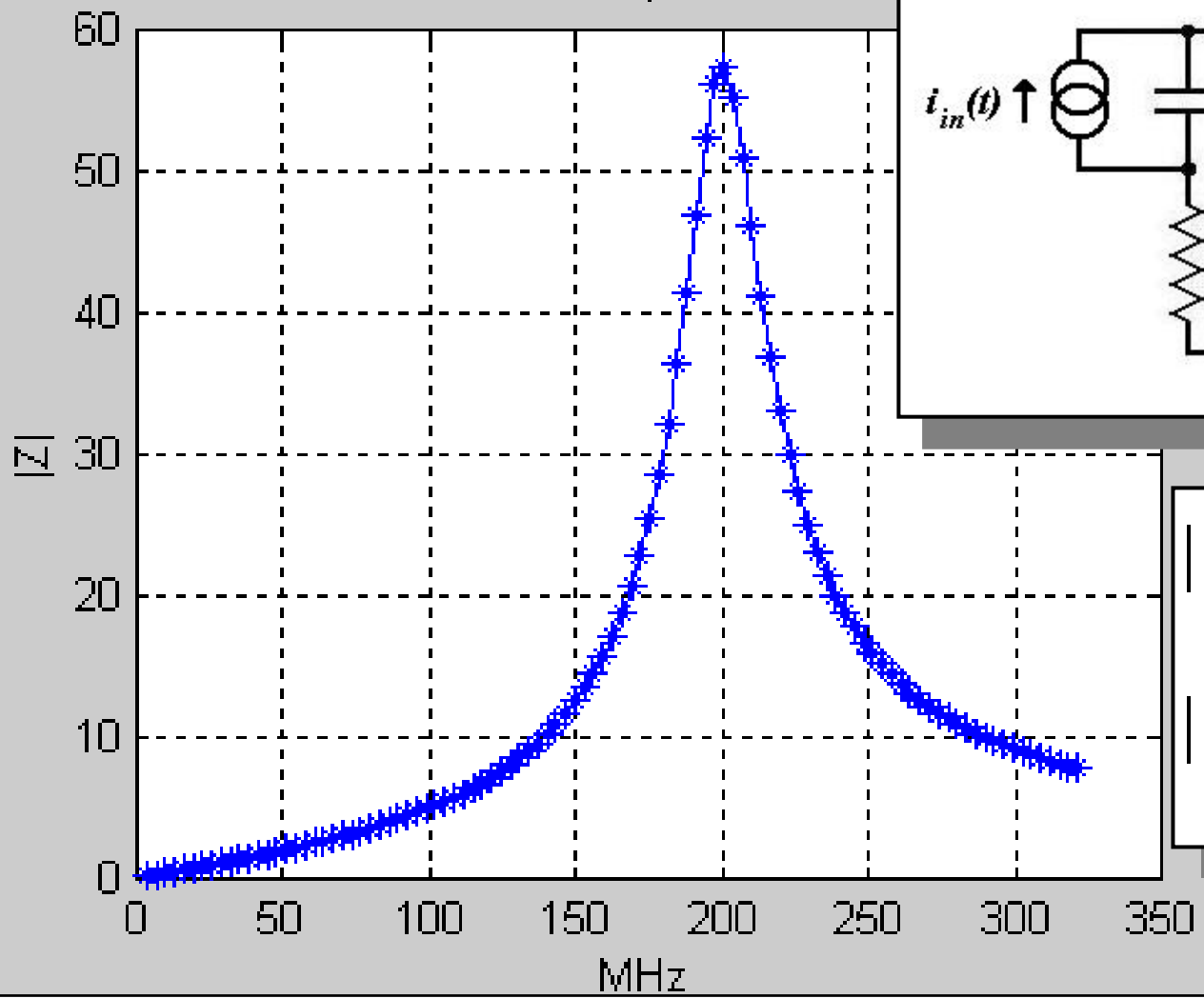
RC- and LCR- Transmittance



LCR- Circuit Impedance

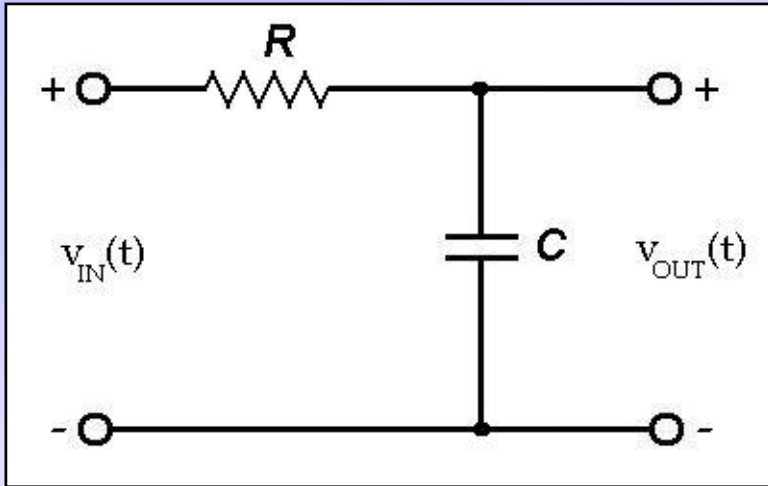


$d=1.5\text{mm}, R=10\Omega\text{m}$

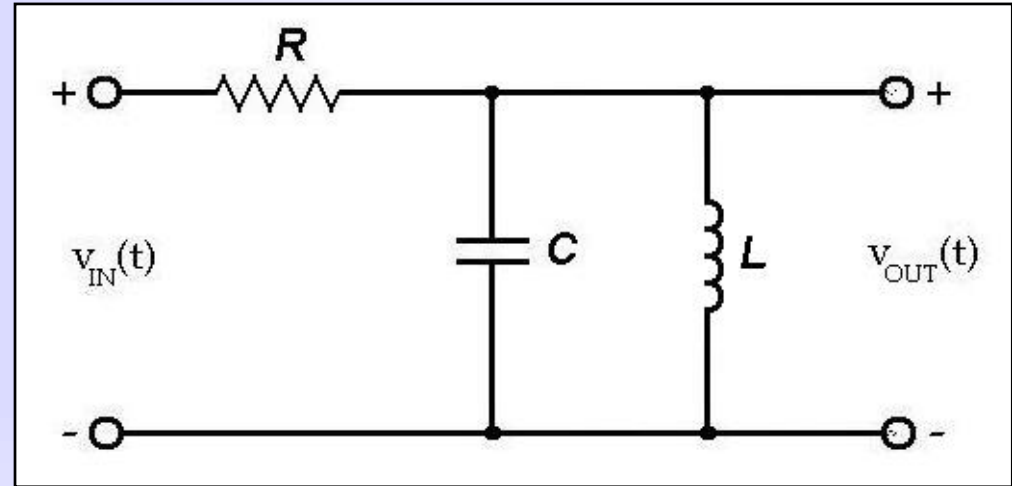


$$\left| \frac{V_{out}}{i_{in}} \right| = |Z|$$
$$|Z_{\omega_0}| = \frac{1}{(\omega_0 C)^2 R_s}$$

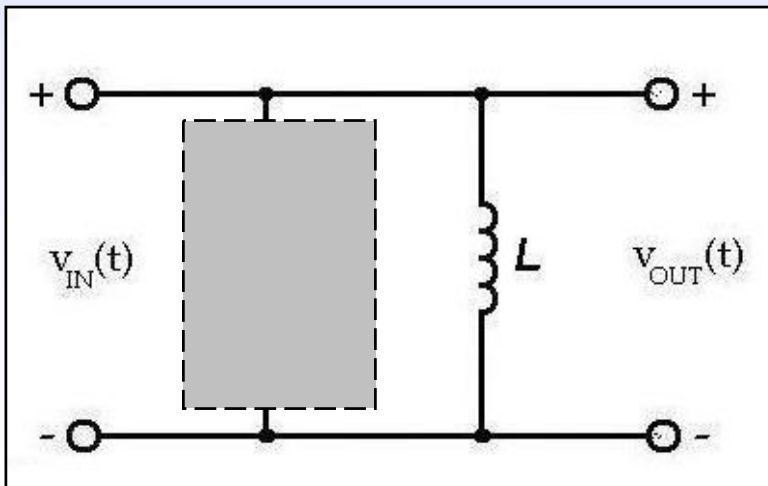
RC- vs. LCR-Circuits



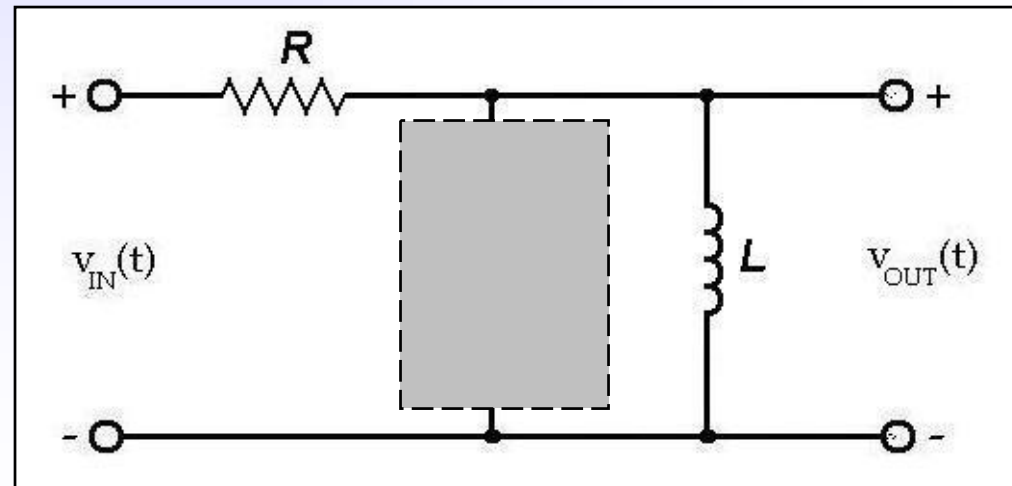
RC- PD acting as a Low-Pass Filter



LCR #1- PD // Inductor as a Tuned Band-Pass Filter (with large $R=50\Omega$)



LCR #2,3- PD // Inductor as a Tuned Band-Pass Filter ($R_s=1\Omega$)



Transfer Function LCR #3

